

## SN74AUP1G08 Low-Power Single 2-Input Positive-AND Gate

### 1 Features

- Available in the Ultra Small 0.64 mm<sup>2</sup> Package (DPW) With 0.5-mm Pitch
- Low Static-Power Consumption:  $I_{CC} = 0.9 \mu A$  Maximum
- Low Dynamic-Power Consumption:  $C_{PD} = 4.3 \text{ pF}$  Typical at 3.3 V
- Low Input Capacitance:  $C_I = 1.5 \text{ pF}$  Typical
- Low Noise: Overshoot and Undershoot <10% of  $V_{CC}$
- $I_{OFF}$  Supports Live Insertion, Partial-Power-Down Mode, and Back Drive Protection
- Schmitt-Trigger Action Allows Slow Input Transition and Better Switching Noise Immunity at the Input ( $V_{HYS} = 250 \text{ mV}$  Typical at 3.3 V)
- Wide Operating  $V_{CC}$  Range of 0.8 V to 3.6 V
- Optimized for 3.3-V Operation
- 3.6-V I/O Tolerant to Support Mixed-Mode Signal Operation
- $t_{PD} = 4.3 \text{ ns}$  Maximum at 3.3 V
- Suitable for Point-to-Point Applications
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Performance Tested Per JESD 22
  - 2000-V Human-Body Model (A114-B, Class II)
  - 1000-V Charged-Device Model (C101)

### Simplified Schematic



### 2 Applications

- ATCA Solutions
- Active Noise Cancellation (ANC)
- Barcode Scanner
- Blood Pressure Monitor
- CPAP Machine
- Cable Solutions
- DLP 3D Machine Vision, Hyperspectral Imaging, Optical Networking, and Spectroscopy
- E-Book
- Embedded PC
- Field Transmitter: Temperature or Pressure Sensor
- Fingerprint Biometrics
- HVAC: Heating, Ventilating, and Air Conditioning
- Network-Attached Storage (NAS)
- Server Motherboard and PSU
- Software Defined Radio (SDR)
- TV: High-Definition (HDTV), LCD, and Digital
- Video Communications System
- Wireless Data Access Card, Headset, Keyboard, Mouse, and LAN Card
- X-ray: Baggage Scanner, Medical, and Dental

### 3 Description

This single 2-input positive-AND gate is designed for 0.8-V to 3.6-V  $V_{CC}$  operation and performs the Boolean function  $Y = A \bullet B$  or  $Y = \overline{A} + \overline{B}$  in positive logic.

### Device Information<sup>(1)</sup>

PART NUMBER	PACKAGE	BODY SIZE (NOM)
SN74AUP1G08DBV	SOT-23 (5)	2.90 mm x 1.60 mm
SN74AUP1G08DRL	SOT (5)	1.60 mm x 1.20 mm
SN74AUP1G08DRY	SON (6)	1.45 mm x 1.00 mm
SN74AUP1G08DPW	X2SON (5)	0.80 mm x 0.80 mm
SN74AUP1G08YZP	DSBGA (5)	1.37 mm x 0.88 mm
SN74AUP1G08DCK	SC70 (5)	1.25 mm x 2.00 mm
SN74AUP1G08DSF	SON (6)	1.00 mm x 1.00 mm
SN74AUP1G08YFP	DSBGA (6)	1.16 mm x 0.76 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.



An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. **PRODUCTION DATA**.

## Table of Contents

<b>1</b>	<b>Features</b>	<b>1</b>	<b>8</b>	<b>Detailed Description</b>	<b>12</b>
<b>2</b>	<b>Applications</b>	<b>1</b>	8.1	Overview	12
<b>3</b>	<b>Description</b>	<b>1</b>	8.2	Functional Block Diagram	12
<b>4</b>	<b>Revision History</b>	<b>2</b>	8.3	Feature Description	12
<b>5</b>	<b>Pin Configuration and Functions</b>	<b>4</b>	8.4	Device Functional Modes	12
<b>6</b>	<b>Specifications</b>	<b>5</b>	<b>9</b>	<b>Application and Implementation</b>	<b>13</b>
6.1	Absolute Maximum Ratings	5	9.1	Application Information	13
6.2	ESD Ratings	5	9.2	Typical Application	13
6.3	Recommended Operating Conditions	5	<b>10</b>	<b>Power Supply Recommendations</b>	<b>14</b>
6.4	Thermal Information	6	<b>11</b>	<b>Layout</b>	<b>14</b>
6.5	Electrical Characteristics	7	11.1	Layout Guidelines	14
6.6	Switching Characteristics, $C_L = 5 \text{ pF}$	7	11.2	Layout Example	14
6.7	Switching Characteristics, $C_L = 10 \text{ pF}$	8	<b>12</b>	<b>Device and Documentation Support</b>	<b>15</b>
6.8	Switching Characteristics, $C_L = 15 \text{ pF}$	8	12.1	Receiving Notification of Documentation Updates	15
6.9	Switching Characteristics, $C_L = 30 \text{ pF}$	8	12.2	Community Resources	15
6.10	Operating Characteristics	8	12.3	Trademarks	15
6.11	Typical Characteristics	9	12.4	Electrostatic Discharge Caution	15
<b>7</b>	<b>Parameter Measurement Information</b>	<b>10</b>	12.5	Glossary	15
7.1	Propagation Delays, Setup and Hold Times, and Pulse Duration	10	<b>13</b>	<b>Mechanical, Packaging, and Orderable Information</b>	<b>15</b>
7.2	Enable and Disable Times	11			

## 4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

### Changes from Revision O (June 2014) to Revision P

		Page
• Updated <i>Applications</i> and <i>Device Information</i> table	1	
• Updated pinout images and <i>Pin Functions</i> table	4	
• Added temperature ranges for Storage temperature, $T_{stg}$ and Junction temperature, $T_J$ in <i>Absolute Maximum Ratings</i>	5	
• Changed <i>Handling Ratings</i> to <i>ESD Ratings</i> and changed MIN, MAX column to a VALUE column	5	
• Added <i>Receiving Notification of Documentation Updates</i> section	15	

### Changes from Revision N (November 2012) to Revision O

		Page
• Updated document to new TI data sheet format	1	
• Removed ordering information	1	
• Added Applications	1	
• Fixed typo in YFP package drawing	4	
• Added <i>Handling Ratings</i> table	5	
• Added Thermal Information table	6	
• Added Typical Characteristics	9	

### Changes from Revision M (September 2012) to Revision N

		Page
• Changed DPW package pinout	4	

**Changes from Revision K (October 2011) to Revision L** **Page**

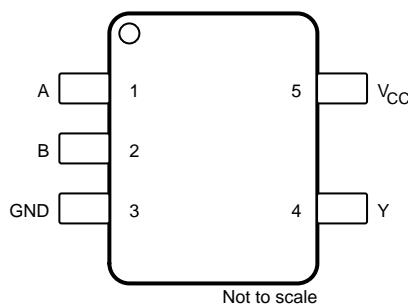
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- Revised document to fix package addendum issue..... 1

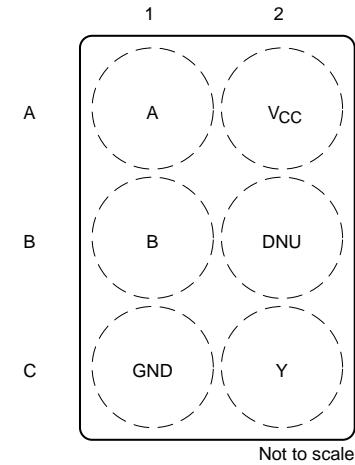
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## 5 Pin Configuration and Functions

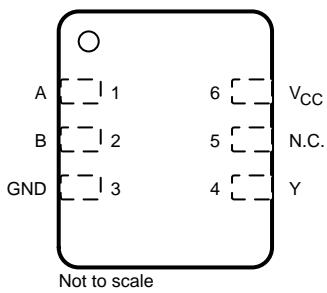
**DRL, DCK, or DBV Packages**  
5-Pin SOT, SC70, or SOT-23  
Top View



**YFP Package**  
6-Pin DSBGA  
Top View

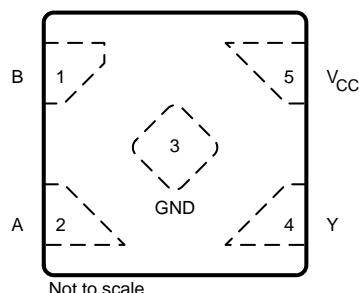


**DRY or DSF Packages**  
6-Pin SON  
Top View

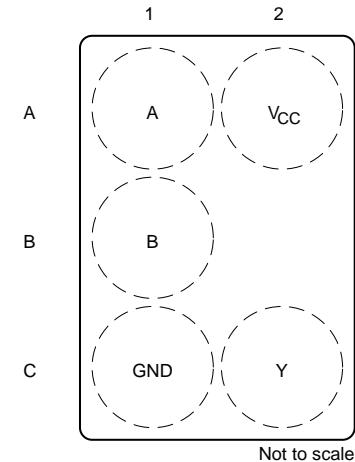


DNU – Do not use

**DPW Package**  
5-PIN X2SON  
Top View



**YZP Package**  
5-Pin DSBGA  
Top View



See mechanical drawings for dimensions.

### Pin Functions

PIN						I/O	DESCRIPTION
NAME	DRL, DCK, DBV	DPW	DRY, DSF	YZP	YFP		
A	1	2	1	A1	A1	I	Input A
B	2	1	2	B1	B1	I	Input B
DNU	–	–	–	–	B2	–	Do not use
GND	3	3	3	C1	C1	–	Ground
N.C.	–	–	5	–	–	–	No internal connection
V <sub>CC</sub>	5	5	6	A2	A2	–	Power Pin
Y	4	4	4	C2	C2	O	Output Y

## 6 Specifications

### 6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) <sup>(1)</sup>

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage	–0.5	4.6	V
V <sub>I</sub>	Input voltage <sup>(2)</sup>	–0.5	4.6	V
V <sub>O</sub>	Voltage range applied to any output in the high-impedance or power-off state <sup>(2)</sup>	–0.5	4.6	V
V <sub>O</sub>	Output voltage range in the high or low state <sup>(2)</sup>	–0.5	V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < 0	–50	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0	–50	mA
I <sub>O</sub>	Continuous output current		±20	mA
	Continuous current through V <sub>CC</sub> or GND		±50	mA
T <sub>J</sub>	Maximum junction temperature		150	°C
T <sub>stg</sub>	Storage temperature	–65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

### 6.2 ESD Ratings

		VALUE	UNIT	
V <sub>(ESD)</sub>	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	2000	V
		Charged device model (CDM), per JEDEC specification JESD22-C101 <sup>(2)</sup>	1000	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted) <sup>(1)</sup>

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage	0.8	3.6	V
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 0.8 V	V <sub>CC</sub>	V
		V <sub>CC</sub> = 1.1 V to 1.95 V	0.65 × V <sub>CC</sub>	
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.6	
		V <sub>CC</sub> = 3 V to 3.6 V	2	

(1) All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. See the TI application report *Implications of Slow or Floating CMOS Inputs*, literature number **SCBA004**.

## Recommended Operating Conditions (continued)

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

			MIN	MAX	UNIT
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 0.8 V		0	V
		V <sub>CC</sub> = 1.1 V to 1.95 V		0.35 × V <sub>CC</sub>	
		V <sub>CC</sub> = 2.3 V to 2.7 V		0.7	
		V <sub>CC</sub> = 3 V to 3.6 V		0.9	
V <sub>I</sub>	Input voltage		0	3.6	V
V <sub>O</sub>	Output voltage		0	V <sub>CC</sub>	V
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 0.8 V		-20	μA
		V <sub>CC</sub> = 1.1 V		-1.1	
		V <sub>CC</sub> = 1.4 V		-1.7	
		V <sub>CC</sub> = 1.65		-1.9	
		V <sub>CC</sub> = 2.3 V		-3.1	
		V <sub>CC</sub> = 3 V		-4	
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 0.8 V		20	mA
		V <sub>CC</sub> = 1.1 V		1.1	
		V <sub>CC</sub> = 1.4 V		1.7	
		V <sub>CC</sub> = 1.65 V		1.9	
		V <sub>CC</sub> = 2.3 V		3.1	
		V <sub>CC</sub> = 3 V		4	
Δt/Δv	Input transition rise or fall rate	V <sub>CC</sub> = 0.8 V to 3.6 V		200	ns/V
T <sub>A</sub>	Operating free-air temperature		-40	85	°C

## 6.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>	SN74AUP1G08						UNIT	
	DBV (SOT-23)	DCK (SC70)	DRL (SOT)	DSF (SON)	DRY (SON)	DPW (X2SON)		
	5 PINS	5 PINS	5 PINS	6 PINS	6 PINS	5 PINS		
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	298.6	314.4	349.7	407.1	554.9	291.8	°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	240.2	128.7	120.5	232	385.4	224.2	°C/W
R <sub>θJB</sub>	Junction-to-board thermal resistance	134.6	100.6	171.4	306.9	388.2	245.8	°C/W
Ψ <sub>JT</sub>	Junction-to-top characterization parameter	114.5	7.1	10.8	40.3	159	245.6	°C/W
Ψ <sub>JB</sub>	Junction-to-board characterization parameter	133.9	99.8	169.4	306	384.1	195.4	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

## 6.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C			T <sub>A</sub> = -40°C to +85°C		UNIT	
			MIN	TYP	MAX	MIN	MAX		
V <sub>OH</sub>	I <sub>OH</sub> = -20 µA	0.8 V to 3.6 V	V <sub>CC</sub> - 0.1			V <sub>CC</sub> - 0.1		V	
	I <sub>OH</sub> = -1.1 mA	1.1 V	0.75 × V <sub>CC</sub>			0.7 × V <sub>CC</sub>			
	I <sub>OH</sub> = -1.7 mA	1.4 V	1.11			1.03			
	I <sub>OH</sub> = -1.9 mA	1.65 V	1.32			1.3			
	I <sub>OH</sub> = -2.3 mA	2.3 V	2.05			1.97			
	I <sub>OH</sub> = -3.1 mA		1.9			1.85			
	I <sub>OH</sub> = -2.7 mA	3 V	2.72			2.67			
	I <sub>OH</sub> = -4 mA		2.6			2.55			
V <sub>OL</sub>	I <sub>OL</sub> = 20 µA	0.8 V to 3.6 V	0.1			0.1		V	
	I <sub>OL</sub> = 1.1 mA	1.1 V	0.3 × V <sub>CC</sub>			0.3 × V <sub>CC</sub>			
	I <sub>OL</sub> = 1.7 mA	1.4 V	0.31			0.37			
	I <sub>OL</sub> = 1.9 mA	1.65 V	0.31			0.35			
	I <sub>OL</sub> = 2.3 mA	2.3 V	0.31			0.33			
	I <sub>OL</sub> = 3.1 mA		0.44			0.45			
	I <sub>OL</sub> = 2.7 mA	3 V	0.31			0.33			
	I <sub>OL</sub> = 4 mA		0.44			0.45			
I <sub>I</sub> A or B input	V <sub>I</sub> = GND to 3.6 V	0 V to 3.6 V	0.1			0.5		µA	
I <sub>off</sub>	V <sub>I</sub> or V <sub>O</sub> = 0 V to 3.6 V	0 V	0.2			0.6		µA	
ΔI <sub>off</sub>	V <sub>I</sub> or V <sub>O</sub> = 0 V to 3.6 V	0 V to 0.2 V	0.2			0.6		µA	
I <sub>CC</sub>	V <sub>I</sub> = GND or (V <sub>CC</sub> to 3.6 V) I <sub>O</sub> = 0	0.8 V to 3.6 V	0.5			0.9		µA	
ΔI <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> - 0.6 V <sup>(1)</sup> I <sub>O</sub> = 0	3.3 V	40			50		µA	
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	0 V	1.5					pF	
		3.6 V	1.5						
C <sub>o</sub>	V <sub>O</sub> = GND	0 V	3					pF	

(1) One input at V<sub>CC</sub> - 0.6 V, other input at V<sub>CC</sub> or GND.

## 6.6 Switching Characteristics, C<sub>L</sub> = 5 pF

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 3](#) and [Figure 4](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub>	T <sub>A</sub> = 25°C			T <sub>A</sub> = -40°C to +85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
t <sub>pd</sub>	A or B	Y	0.8 V	18					ns
			1.2 V ± 0.1 V	2.6	7.3	12.8	2.1	15.6	
			1.5 V ± 0.1 V	1.4	5.2	8.7	0.9	10.3	
			1.8 V ± 0.15 V	1	4.2	6.6	0.5	8.2	
			2.5 V ± 0.2 V	1	3	4.4	0.5	5.5	
			3.3 V ± 0.3 V	1	2.4	3.5	0.5	4.3	

## 6.7 Switching Characteristics, $C_L = 10 \text{ pF}$

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 3](#) and [Figure 4](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}$	$T_A = 25^\circ\text{C}$			$T_A = -40^\circ\text{C} \text{ to } +85^\circ\text{C}$		UNIT
				MIN	TYP	MAX	MIN	MAX	
$t_{pd}$	A or B	Y	0.8 V	21					ns
			$1.2 \text{ V} \pm 0.1 \text{ V}$	1.5	8.5	14.7	1	17.2	
			$1.5 \text{ V} \pm 0.1 \text{ V}$	1	6.2	10	0.5	11.3	
			$1.8 \text{ V} \pm 0.15 \text{ V}$	1	5	7.7	0.5	9	
			$2.5 \text{ V} \pm 0.2 \text{ V}$	1	3.6	5.2	0.5	6.1	
			$3.3 \text{ V} \pm 0.3 \text{ V}$	1	2.9	4.2	0.5	4.7	

## 6.8 Switching Characteristics, $C_L = 15 \text{ pF}$

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 3](#) and [Figure 4](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}$	$T_A = 25^\circ\text{C}$			$T_A = -40^\circ\text{C} \text{ to } +85^\circ\text{C}$		UNIT
				MIN	TYP	MAX	MIN	MAX	
$t_{pd}$	A or B	Y	0.8 V	24					ns
			$1.2 \text{ V} \pm 0.1 \text{ V}$	3.6	9.9	16.3	3.1	19.9	
			$1.5 \text{ V} \pm 0.1 \text{ V}$	2.3	7.2	11.1	1.8	13.2	
			$1.8 \text{ V} \pm 0.15 \text{ V}$	1.6	5.8	8.7	1.1	10.6	
			$2.5 \text{ V} \pm 0.2 \text{ V}$	1	4.3	5.9	0.5	7.3	
			$3.3 \text{ V} \pm 0.3 \text{ V}$	1	3.4	4.8	0.5	5.9	

## 6.9 Switching Characteristics, $C_L = 30 \text{ pF}$

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 3](#) and [Figure 4](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}$	$T_A = 25^\circ\text{C}$			$T_A = -40^\circ\text{C} \text{ to } +85^\circ\text{C}$		UNIT
				MIN	TYP	MAX	MIN	MAX	
$t_{pd}$	A or B	Y	0.8 V	32.8					ns
			$1.2 \text{ V} \pm 0.1 \text{ V}$	4.9	13.1	20.9	4.4	25.5	
			$1.5 \text{ V} \pm 0.1 \text{ V}$	3.4	9.5	14.2	2.9	16.9	
			$1.8 \text{ V} \pm 0.15 \text{ V}$	2.5	7.7	11	2	13.5	
			$2.5 \text{ V} \pm 0.2 \text{ V}$	1.8	5.7	7.6	1.3	9.4	
			$3.3 \text{ V} \pm 0.3 \text{ V}$	1.5	4.7	6.2	1	7.5	

## 6.10 Operating Characteristics

 $T_A = 25^\circ\text{C}$ 

PARAMETER			TEST CONDITIONS			$V_{CC}$	TYP	UNIT
$C_{pd}$	Power dissipation capacitance		$f = 10 \text{ MHz}$			0.8 V	4	pF
						$1.2 \text{ V} \pm 0.1 \text{ V}$	4	
						$1.5 \text{ V} \pm 0.1 \text{ V}$	4	
						$1.8 \text{ V} \pm 0.15 \text{ V}$	4	
						$2.5 \text{ V} \pm 0.2 \text{ V}$	4.1	
						$3.3 \text{ V} \pm 0.3 \text{ V}$	4.3	

## 6.11 Typical Characteristics

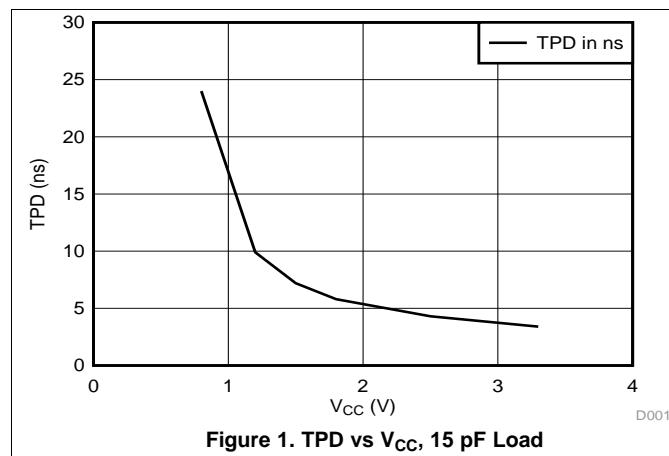


Figure 1. TPD vs  $V_{CC}$ , 15 pF Load

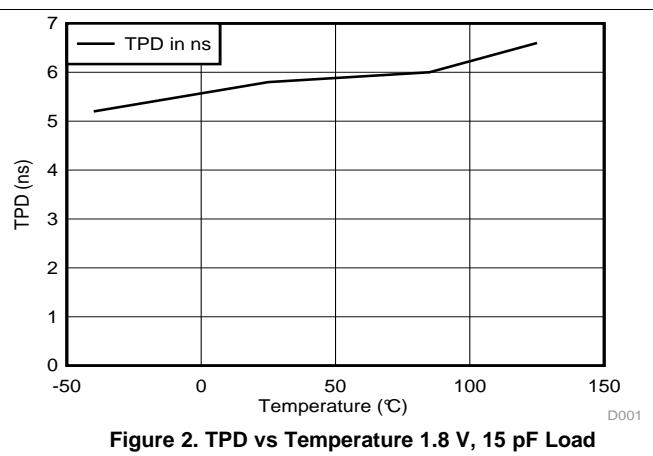
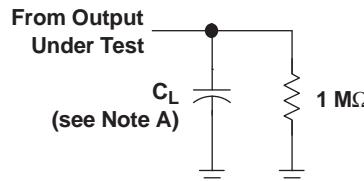


Figure 2. TPD vs Temperature 1.8 V, 15 pF Load

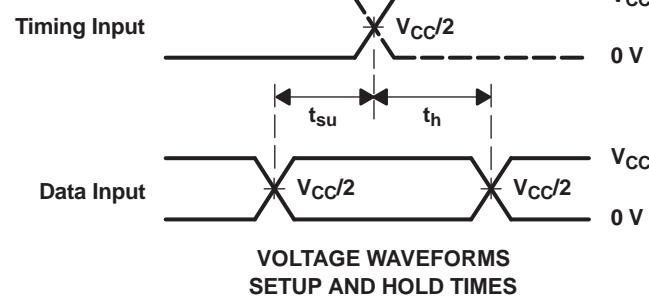
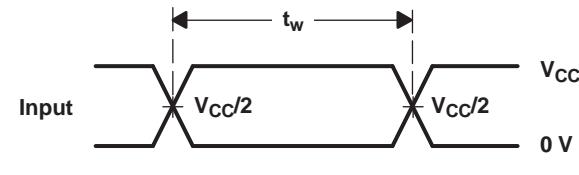
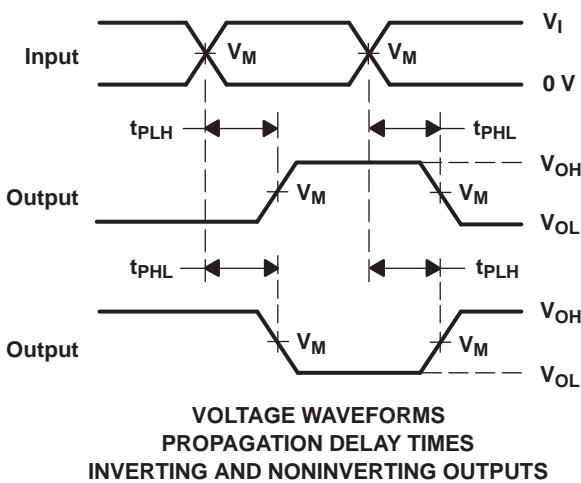
## 7 Parameter Measurement Information

### 7.1 Propagation Delays, Setup and Hold Times, and Pulse Duration



LOAD CIRCUIT

	$V_{CC} = 0.8 \text{ V}$	$V_{CC} = 1.2 \text{ V} \pm 0.1 \text{ V}$	$V_{CC} = 1.5 \text{ V} \pm 0.1 \text{ V}$	$V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$	$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$
$C_L$	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF
$V_M$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$
$V_I$	$V_{CC}$	$V_{CC}$	$V_{CC}$	$V_{CC}$	$V_{CC}$	$V_{CC}$

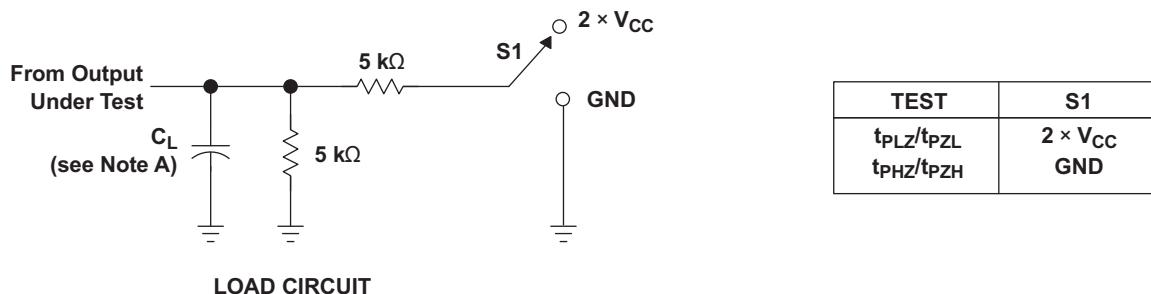


NOTES:

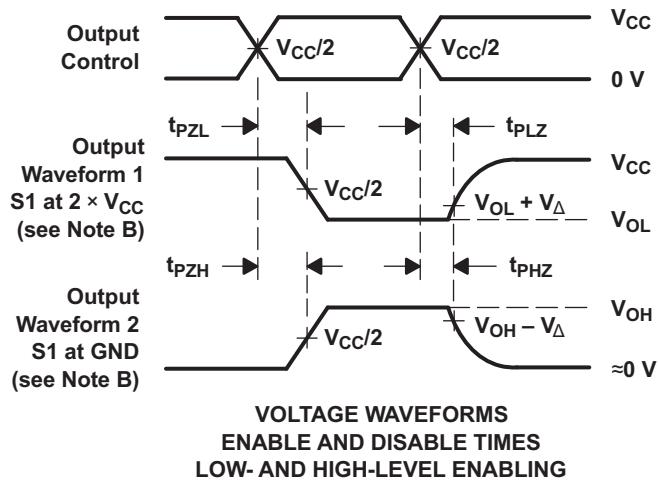
- $C_L$  includes probe and jig capacitance.
- All input pulses are supplied by generators having the following characteristics: PRR  $\leq 10 \text{ MHz}$ ,  $Z_O = 50 \Omega$ , slew rate  $\geq 1 \text{ V/ns}$ .
- The outputs are measured one at a time, with one transition per measurement.
- $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- All parameters and waveforms are not applicable to all devices.

Figure 3. Load Circuit and Voltage Waveforms

## 7.2 Enable and Disable Times



	$V_{CC} = 0.8 \text{ V}$	$V_{CC} = 1.2 \text{ V} \pm 0.1 \text{ V}$	$V_{CC} = 1.5 \text{ V} \pm 0.1 \text{ V}$	$V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$	$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$
$C_L$	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF
$V_M$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$
$V_I$	$V_{CC}$	$V_{CC}$	$V_{CC}$	$V_{CC}$	$V_{CC}$	$V_{CC}$
$V_\Delta$	0.1 V	0.1 V	0.1 V	0.15 V	0.15 V	0.3 V



NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10 \text{ MHz}$ ,  $Z_O = 50 \Omega$ , slew rate  $\geq 1 \text{ V/ns}$ .  
 D. The outputs are measured one at a time, with one transition per measurement.  
 E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .  
 F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .  
 G. All parameters and waveforms are not applicable to all devices.

**Figure 4. Load Circuit and Voltage Waveforms**

## 8 Detailed Description

### 8.1 Overview

This single 2-input positive-AND gate is designed for 0.8-V to 3.6-V  $V_{CC}$  operation and performs the Boolean function  $Y = A \bullet B$  or  $Y = \overline{\overline{A}} + \overline{\overline{B}}$  in positive logic.

The AUP family of devices has quiescent power consumption less than 1  $\mu$ A and comes in the ultra small DPW package. The DPW package technology is a major breakthrough in IC packaging. Its tiny 0.64 mm<sup>2</sup> square footprint saves significant board space over other package options while still retaining the traditional manufacturing friendly lead pitch of 0.5 mm.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered. The  $I_{off}$  feature also allows for live insertion.

### 8.2 Functional Block Diagram



### 8.3 Feature Description

- Wide operating  $V_{CC}$  range of 0.8 V to 3.6 V
- 3.6-V I/O tolerant to support down translation
- Input hysteresis allows slow input transition and better switching noise immunity at the input
- $I_{off}$  feature allows voltages on the inputs and outputs when  $V_{CC}$  is 0 V
- Low noise due to slower edge rates

### 8.4 Device Functional Modes

Table 1. Function Table

INPUTS		OUTPUT
A	B	Y
L	L	L
L	H	L
H	L	L
H	H	H

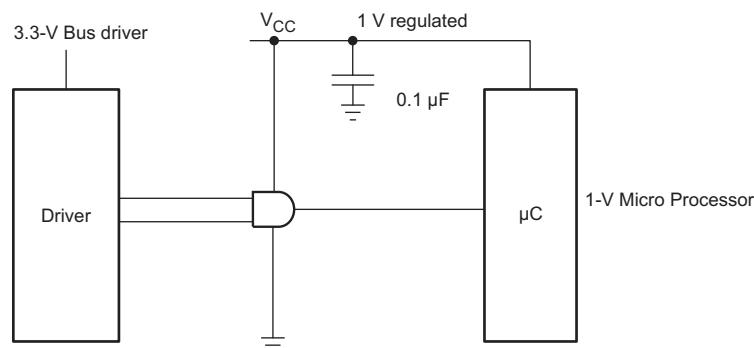
## 9 Application and Implementation

### 9.1 Application Information

The AUP family is TI's premier solution to the industry's low-power needs in battery-powered portable applications. This family ensures a very low static and dynamic power consumption across the entire  $V_{CC}$  range of 0.8 V to 3.6 V, resulting in an increased battery life. This product also maintains excellent signal integrity. It has a small amount of hysteresis built in allowing for slower or noisy input signals. The lowered drive produces slower edges and prevents overshoot and undershoot on the outputs.

The AUP family of single gate logic makes excellent translators for the new lower voltage Micro- processors that typically are powered from 0.8 V to 1.2 V. They can drop the voltage of peripheral drivers and accessories that are still powered by 3.3 V to the new  $\mu$ C power levels.

### 9.2 Typical Application



**Figure 5. Typical Application Schematic**

#### 9.2.1 Design Requirements

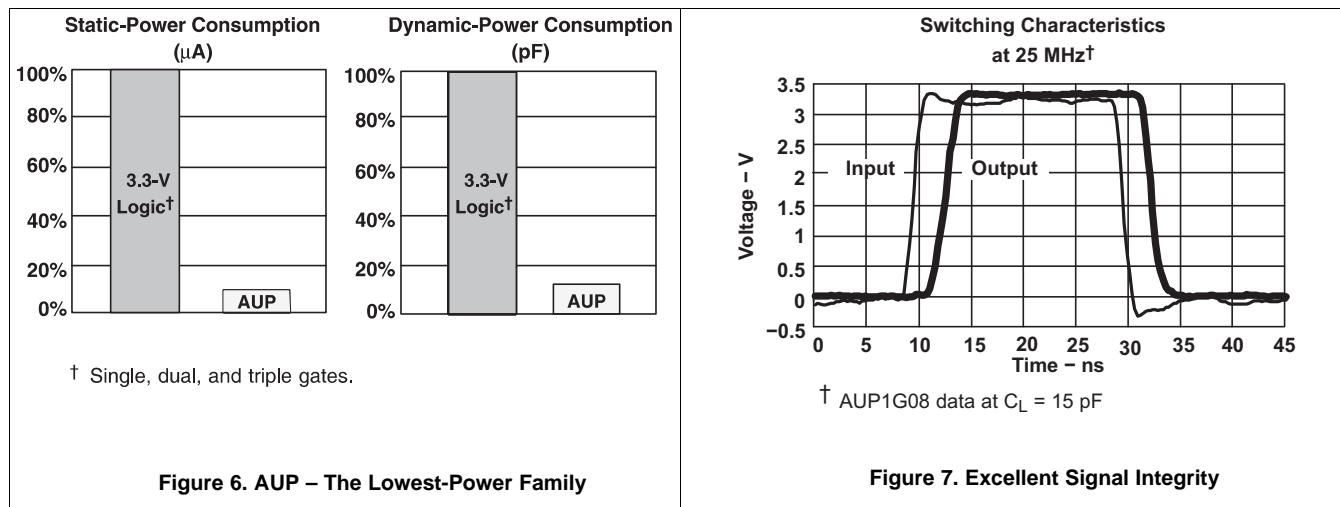
SN74AUP1G08 device uses CMOS technology and has balanced output drive. Take care to avoid bus contention because it can drive currents that would exceed maximum limits.

#### 9.2.2 Detailed Design Procedure

1. Recommended Input conditions
  - Rise time and fall time specifications. See  $(\Delta t/\Delta V)$  in [Recommended Operating Conditions](#) table.
  - Specified high and low levels. See  $(V_{IH}$  and  $V_{IL}$ ) in [Recommended Operating Conditions](#) table.
  - Inputs are overvoltage tolerant allowing them to go as high as 3.6 V at any valid  $V_{CC}$
2. Recommended output conditions
  - Load currents should not exceed 20 mA on the output and 50 mA total for the part
  - Outputs should not be pulled above  $V_{CC}$

## Typical Application (continued)

### 9.2.3 Application Curves



## 10 Power Supply Recommendations

The power supply can be any voltage between the Min and Max supply voltage rating located in the *Recommended Operating Conditions* table.

Each  $V_{CC}$  terminal should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, 0.1  $\mu\text{F}$  is recommended and if there are multiple  $V_{CC}$  terminals then 0.01  $\mu\text{F}$  or 0.022  $\mu\text{F}$  is recommended for each power terminal. It is ok to parallel multiple bypass caps to reject different frequencies of noise. A 0.1  $\mu\text{F}$  and 1  $\mu\text{F}$  are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results.

## 11 Layout

### 11.1 Layout Guidelines

When using multiple bit logic devices inputs should not ever float.

In many cases, functions or parts of functions of digital logic devices are unused, for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. Specified in Figure 8 are the rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or  $V_{CC}$  whichever make more sense or is more convenient. It is generally OK to float outputs unless the part is a transceiver. If the transceiver has an output enable pin it will disable the outputs section of the part when asserted. This will not disable the input section of the I/Os so they also cannot float when disabled.

### 11.2 Layout Example

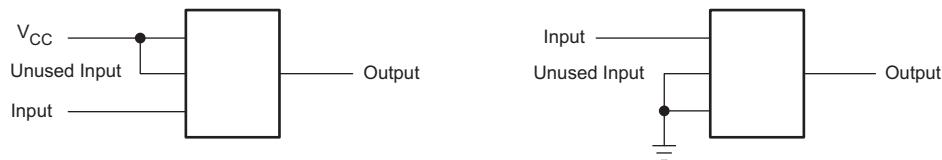


Figure 8. Layout Diagram

## 12 Device and Documentation Support

### 12.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates — go to the product folder for your device on [ti.com](http://ti.com). In the upper right-hand corner, click the *Alert me* button to register and receive a weekly digest of product information that has changed (if any). For change details, check the revision history of any revised document.

### 12.2 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

**TI E2E™ Online Community** *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At [e2e.ti.com](http://e2e.ti.com), you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

**Design Support** *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

### 12.3 Trademarks

E2E is a trademark of Texas Instruments.

All other trademarks are the property of their respective owners.

### 12.4 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

### 12.5 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## 13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74AUP1G08DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	NIPDAU   SN	Level-1-260C-UNLIM	-40 to 85	(H08F, H08R)	<span style="background-color: red; color: white; padding: 2px;">Samples</span>
SN74AUP1G08DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	H08R	<span style="background-color: red; color: white; padding: 2px;">Samples</span>
SN74AUP1G08DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	H08R	<span style="background-color: red; color: white; padding: 2px;">Samples</span>
SN74AUP1G08DCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(HE5, HEF, HEK, HE R) (HEH, HEP, HES)	<span style="background-color: red; color: white; padding: 2px;">Samples</span>
SN74AUP1G08DCKRE4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(HE5, HEF, HEK, HE R) (HEH, HEP, HES)	<span style="background-color: red; color: white; padding: 2px;">Samples</span>
SN74AUP1G08DCKRG4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(HE5, HEF, HEK, HE R) (HEH, HEP, HES)	<span style="background-color: red; color: white; padding: 2px;">Samples</span>
SN74AUP1G08DCKT	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(HE5, HER)	<span style="background-color: red; color: white; padding: 2px;">Samples</span>
SN74AUP1G08DPWR	ACTIVE	X2SON	DPW	5	3000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	E4	<span style="background-color: red; color: white; padding: 2px;">Samples</span>
SN74AUP1G08DRLR	ACTIVE	SOT-5X3	DRL	5	4000	Green (RoHS & no Sb/Br)	NIPDAU   NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	(HE7, HER)	<span style="background-color: red; color: white; padding: 2px;">Samples</span>
SN74AUP1G08DRY2	ACTIVE	SON	DRY	6	5000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HE	<span style="background-color: red; color: white; padding: 2px;">Samples</span>
SN74AUP1G08DRYR	ACTIVE	SON	DRY	6	5000	Green (RoHS & no Sb/Br)	NIPDAU   NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	HE	<span style="background-color: red; color: white; padding: 2px;">Samples</span>
SN74AUP1G08DSF2	ACTIVE	SON	DSF	6	5000	Green (RoHS & no Sb/Br)	NIPDAU   NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	(HE, HER) HEH	<span style="background-color: red; color: white; padding: 2px;">Samples</span>
SN74AUP1G08DSFR	ACTIVE	SON	DSF	6	5000	Green (RoHS & no Sb/Br)	NIPDAU   NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	(HE, HER) HEH	<span style="background-color: red; color: white; padding: 2px;">Samples</span>
SN74AUP1G08YFPR	ACTIVE	DSBGA	YFP	6	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	HEN	<span style="background-color: red; color: white; padding: 2px;">Samples</span>
SN74AUP1G08YZPR	ACTIVE	DSBGA	YZP	5	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	(HE7, HEN)	<span style="background-color: red; color: white; padding: 2px;">Samples</span>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

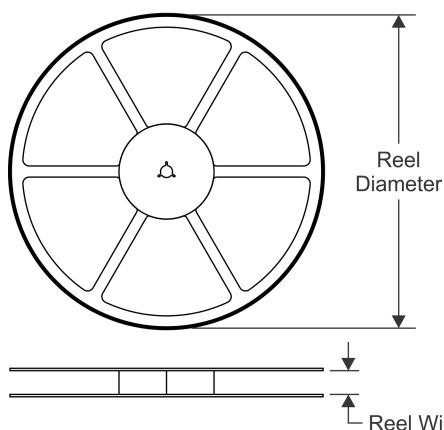
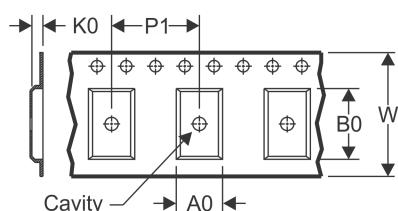
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF SN74AUP1G08 :**

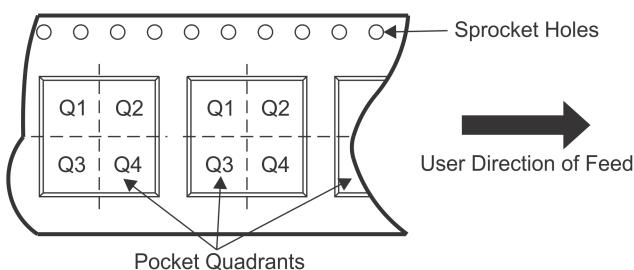
- Automotive: [SN74AUP1G08-Q1](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


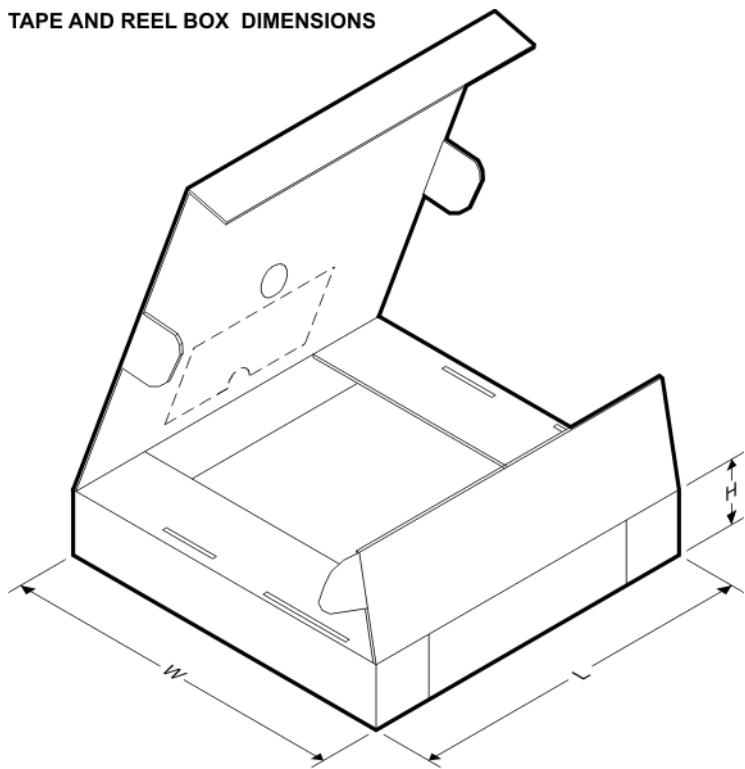
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AUP1G08DBVR	SOT-23	DBV	5	3000	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
SN74AUP1G08DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
SN74AUP1G08DBVT	SOT-23	DBV	5	250	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
SN74AUP1G08DCKR	SC70	DCK	5	3000	178.0	9.2	2.4	2.4	1.22	4.0	8.0	Q3
SN74AUP1G08DCKR	SC70	DCK	5	3000	180.0	8.4	2.47	2.3	1.25	4.0	8.0	Q3
SN74AUP1G08DCKT	SC70	DCK	5	250	178.0	9.2	2.4	2.4	1.22	4.0	8.0	Q3
SN74AUP1G08DCKT	SC70	DCK	5	250	180.0	8.4	2.47	2.3	1.25	4.0	8.0	Q3
SN74AUP1G08DPWWR	X2SON	DPW	5	3000	178.0	8.4	0.91	0.91	0.5	2.0	8.0	Q3
SN74AUP1G08DRLR	SOT-5X3	DRL	5	4000	180.0	8.4	1.98	1.78	0.69	4.0	8.0	Q3
SN74AUP1G08DRLR	SOT-5X3	DRL	5	4000	180.0	9.5	1.78	1.78	0.69	4.0	8.0	Q3
SN74AUP1G08DRY2	SON	DRY	6	5000	180.0	9.5	1.15	1.6	0.75	4.0	8.0	Q3
SN74AUP1G08DRYR	SON	DRY	6	5000	180.0	9.5	1.15	1.6	0.75	4.0	8.0	Q1
SN74AUP1G08DRYR	SON	DRY	6	5000	180.0	8.4	1.25	1.6	0.7	4.0	8.0	Q1
SN74AUP1G08DSF2	SON	DSF	6	5000	180.0	8.4	1.16	1.16	0.63	4.0	8.0	Q3
SN74AUP1G08DSF2	SON	DSF	6	5000	180.0	9.5	1.16	1.16	0.5	4.0	8.0	Q3
SN74AUP1G08DSFR	SON	DSF	6	5000	180.0	9.5	1.16	1.16	0.5	4.0	8.0	Q2
SN74AUP1G08DSFR	SON	DSF	6	5000	180.0	8.4	1.16	1.16	0.63	4.0	8.0	Q2
SN74AUP1G08YFPR	DSBGA	YFP	6	3000	178.0	9.2	0.89	1.29	0.62	4.0	8.0	Q1

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AUP1G08YZPR	DSBGA	YZP	5	3000	178.0	9.2	1.02	1.52	0.63	4.0	8.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

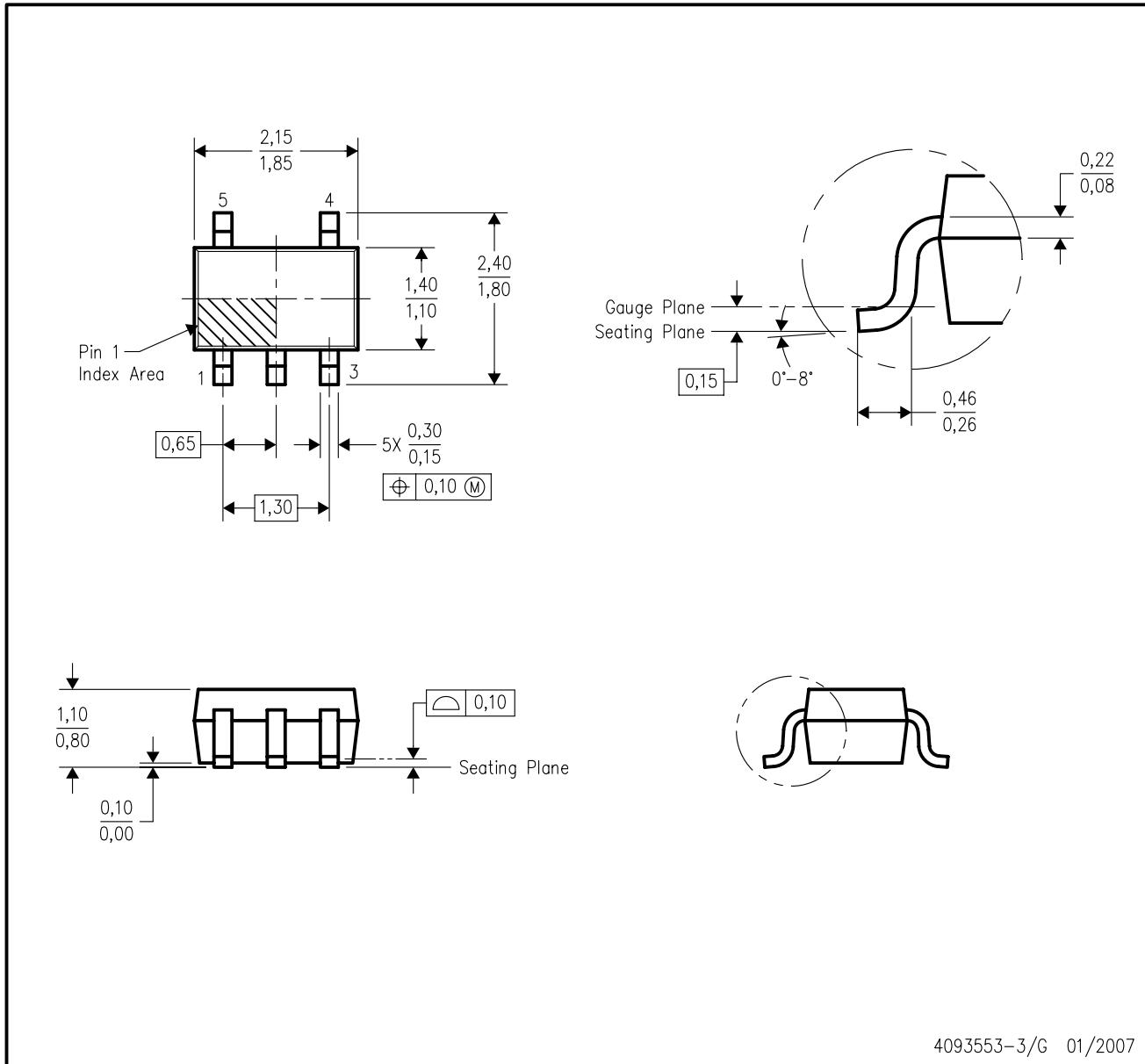
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AUP1G08DBVR	SOT-23	DBV	5	3000	202.0	201.0	28.0
SN74AUP1G08DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
SN74AUP1G08DBVT	SOT-23	DBV	5	250	202.0	201.0	28.0
SN74AUP1G08DCKR	SC70	DCK	5	3000	180.0	180.0	18.0
SN74AUP1G08DCKR	SC70	DCK	5	3000	202.0	201.0	28.0
SN74AUP1G08DCKT	SC70	DCK	5	250	180.0	180.0	18.0
SN74AUP1G08DCKT	SC70	DCK	5	250	202.0	201.0	28.0
SN74AUP1G08DPWR	X2SON	DPW	5	3000	205.0	200.0	33.0
SN74AUP1G08DRLR	SOT-5X3	DRL	5	4000	202.0	201.0	28.0
SN74AUP1G08DRLR	SOT-5X3	DRL	5	4000	184.0	184.0	19.0
SN74AUP1G08DRY2	SON	DRY	6	5000	184.0	184.0	19.0
SN74AUP1G08DRYR	SON	DRY	6	5000	184.0	184.0	19.0
SN74AUP1G08DRYR	SON	DRY	6	5000	202.0	201.0	28.0
SN74AUP1G08DSF2	SON	DSF	6	5000	202.0	201.0	28.0
SN74AUP1G08DSF2	SON	DSF	6	5000	184.0	184.0	19.0
SN74AUP1G08DSFR	SON	DSF	6	5000	184.0	184.0	19.0

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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AUP1G08DSFR	SON	DSF	6	5000	202.0	201.0	28.0
SN74AUP1G08YFPR	DSBGA	YFP	6	3000	220.0	220.0	35.0
SN74AUP1G08YZPR	DSBGA	YZP	5	3000	220.0	220.0	35.0

## DCK (R-PDSO-G5)

## PLASTIC SMALL-OUTLINE PACKAGE



4093553-3/G 01/2007

NOTES:

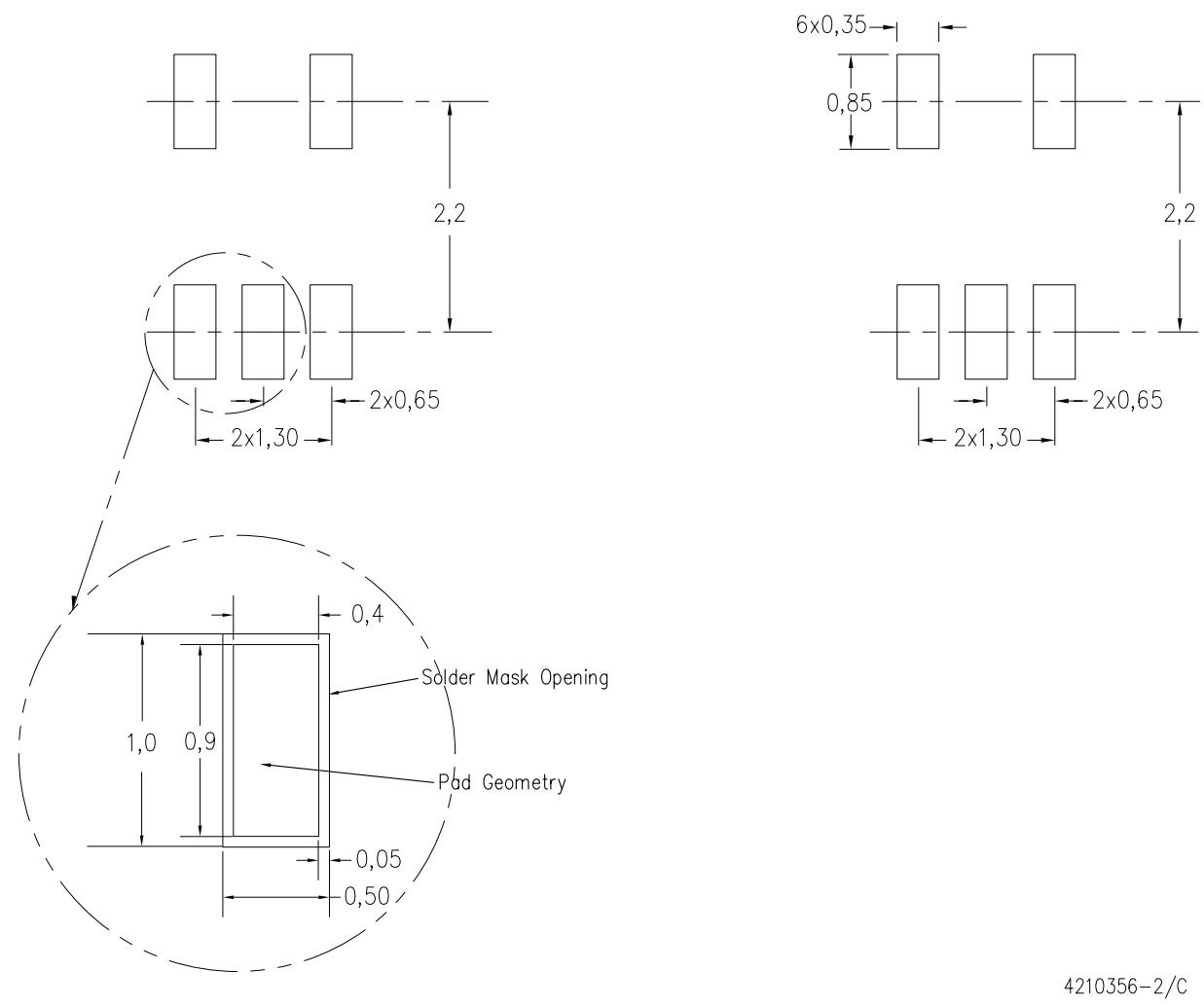
- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- Falls within JEDEC MO-203 variation AA.

DCK (R-PDSO-G5)

PLASTIC SMALL OUTLINE

Example Board Layout

Stencil Openings  
Based on a stencil thickness  
of .127mm (.005inch).



NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- Publication IPC-7351 is recommended for alternate designs.
- Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

DRY 6

## GENERIC PACKAGE VIEW

### USON - 0.6 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4207181/G

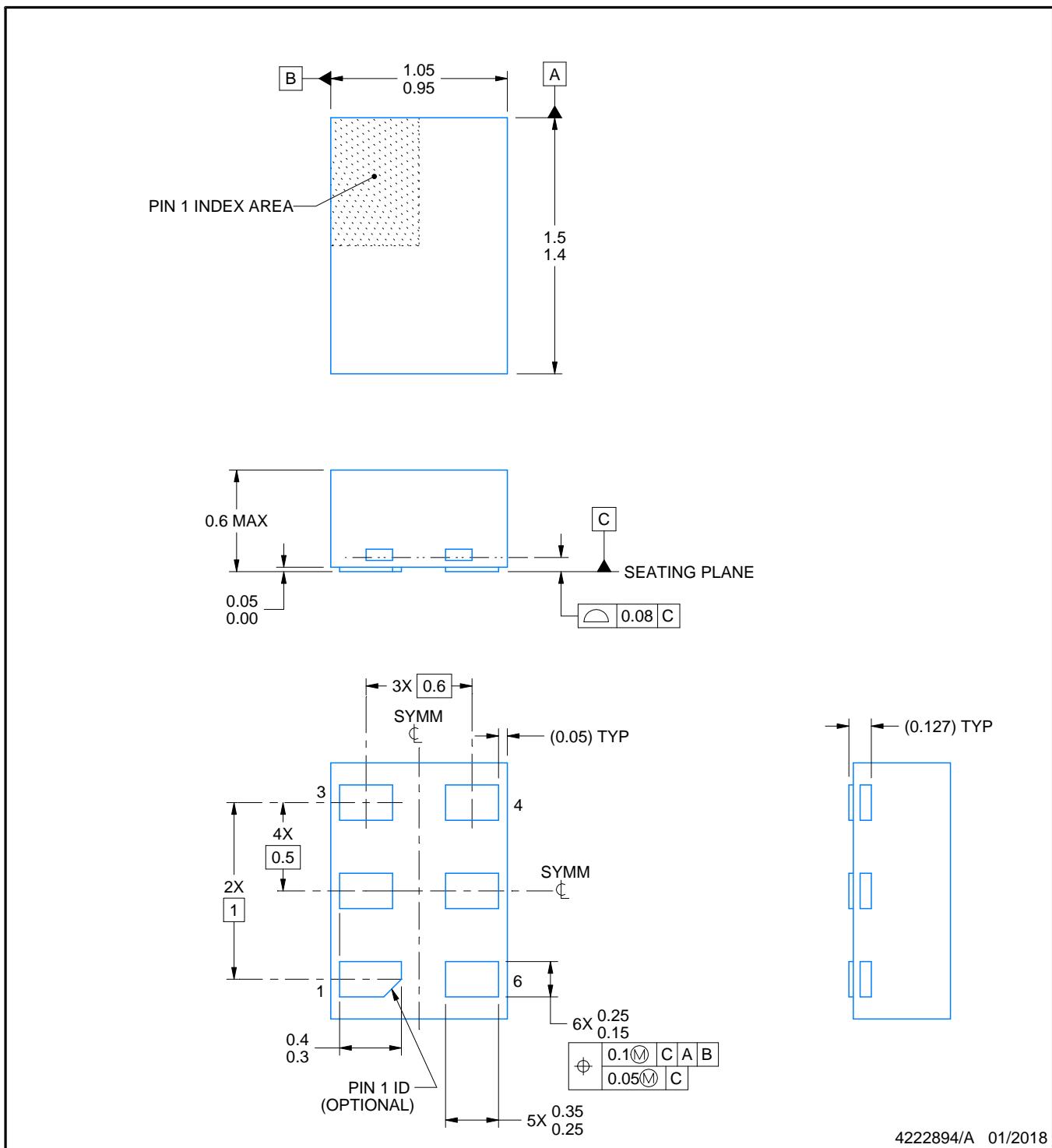
# PACKAGE OUTLINE

DRY0006A



USON - 0.6 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



4222894/A 01/2018

## NOTES:

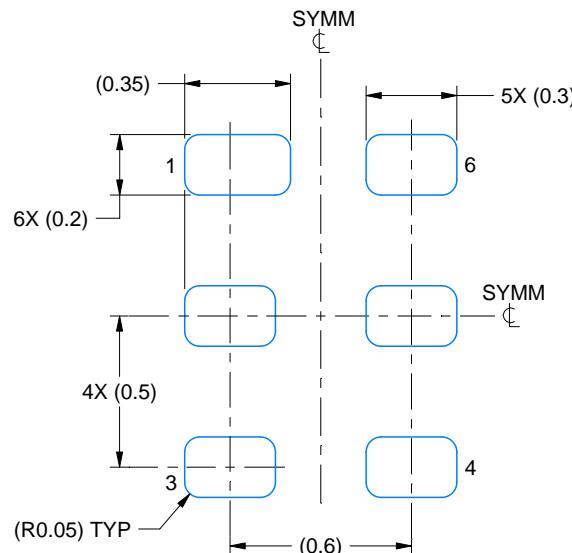
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

# EXAMPLE BOARD LAYOUT

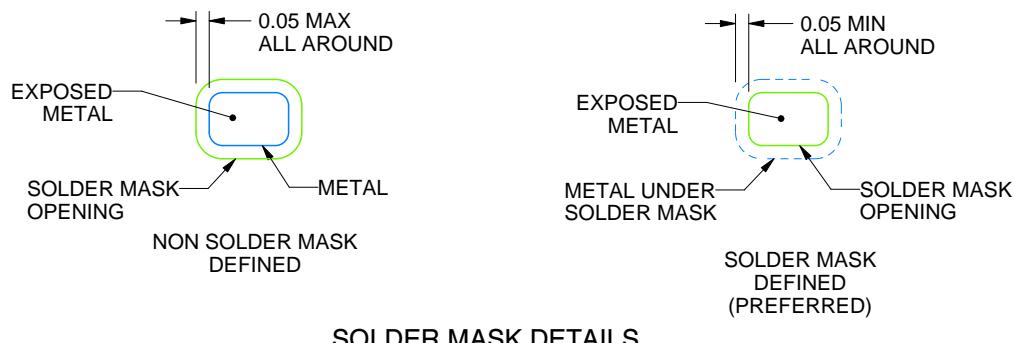
DRY0006A

USON - 0.6 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



LAND PATTERN EXAMPLE  
1:1 RATIO WITH PKG SOLDER PADS  
EXPOSED METAL SHOWN  
SCALE:40X



SOLDER MASK DETAILS

4222894/A 01/2018

NOTES: (continued)

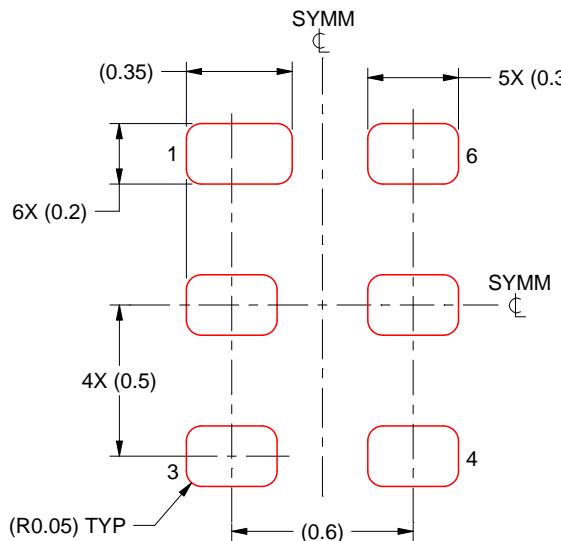
3. For more information, see QFN/SON PCB application report in literature No. SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).

# EXAMPLE STENCIL DESIGN

DRY0006A

USON - 0.6 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE  
BASED ON 0.075 - 0.1 mm THICK STENCIL  
SCALE:40X

4222894/A 01/2018

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

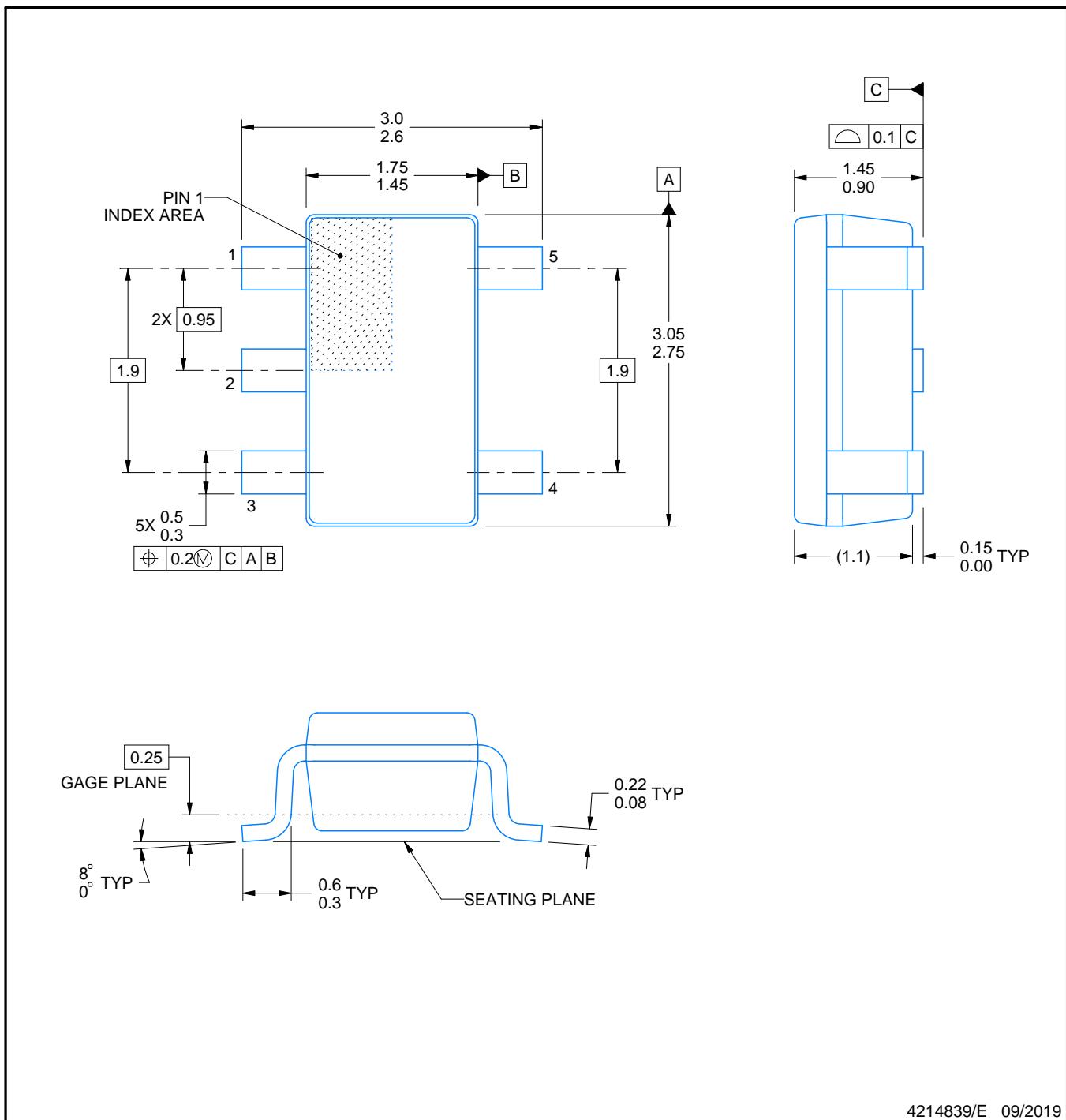
# PACKAGE OUTLINE

DBV0005A



SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



4214839/E 09/2019

## NOTES:

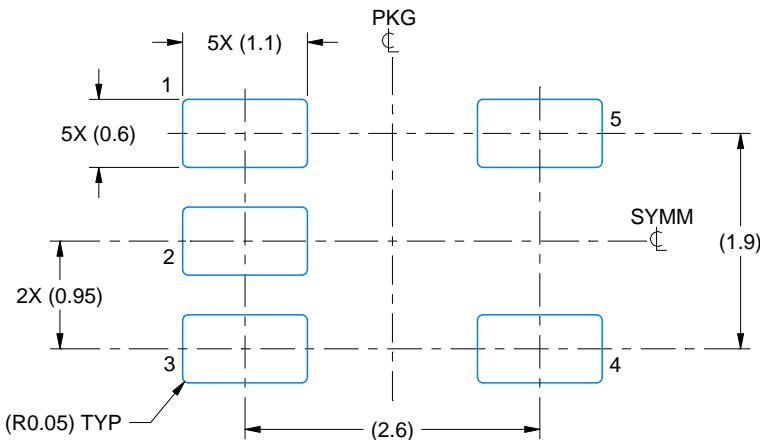
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC MO-178.
4. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.

# EXAMPLE BOARD LAYOUT

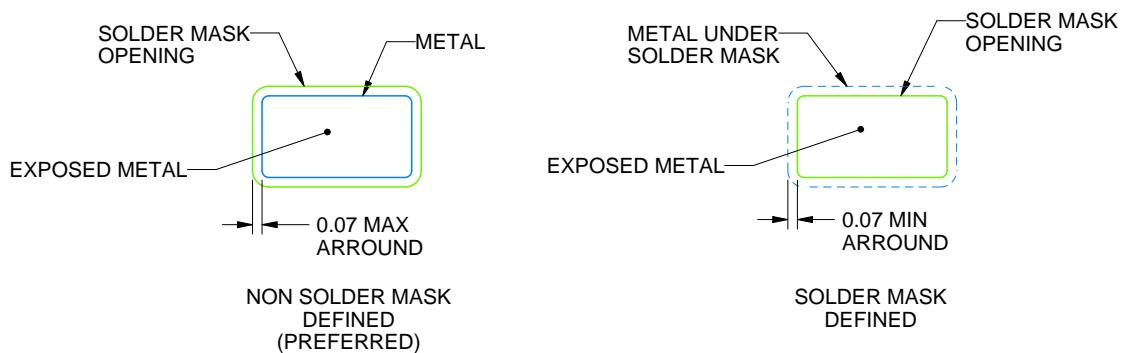
DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:15X



SOLDER MASK DETAILS

4214839/E 09/2019

NOTES: (continued)

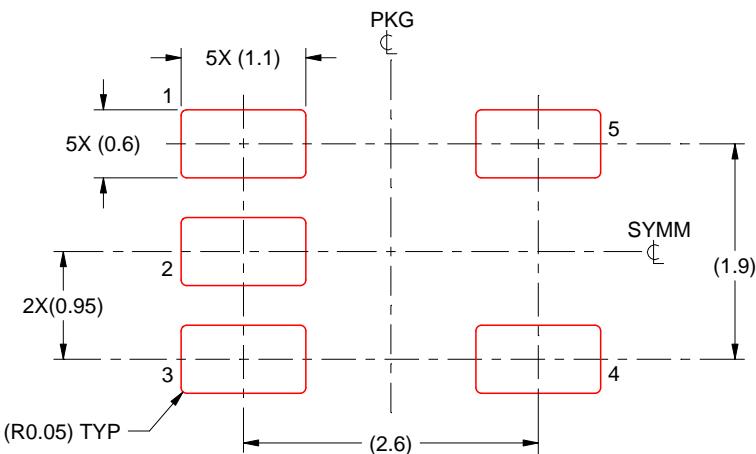
5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:15X

4214839/E 09/2019

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

## GENERIC PACKAGE VIEW

DPW 5

X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4211218-3/D

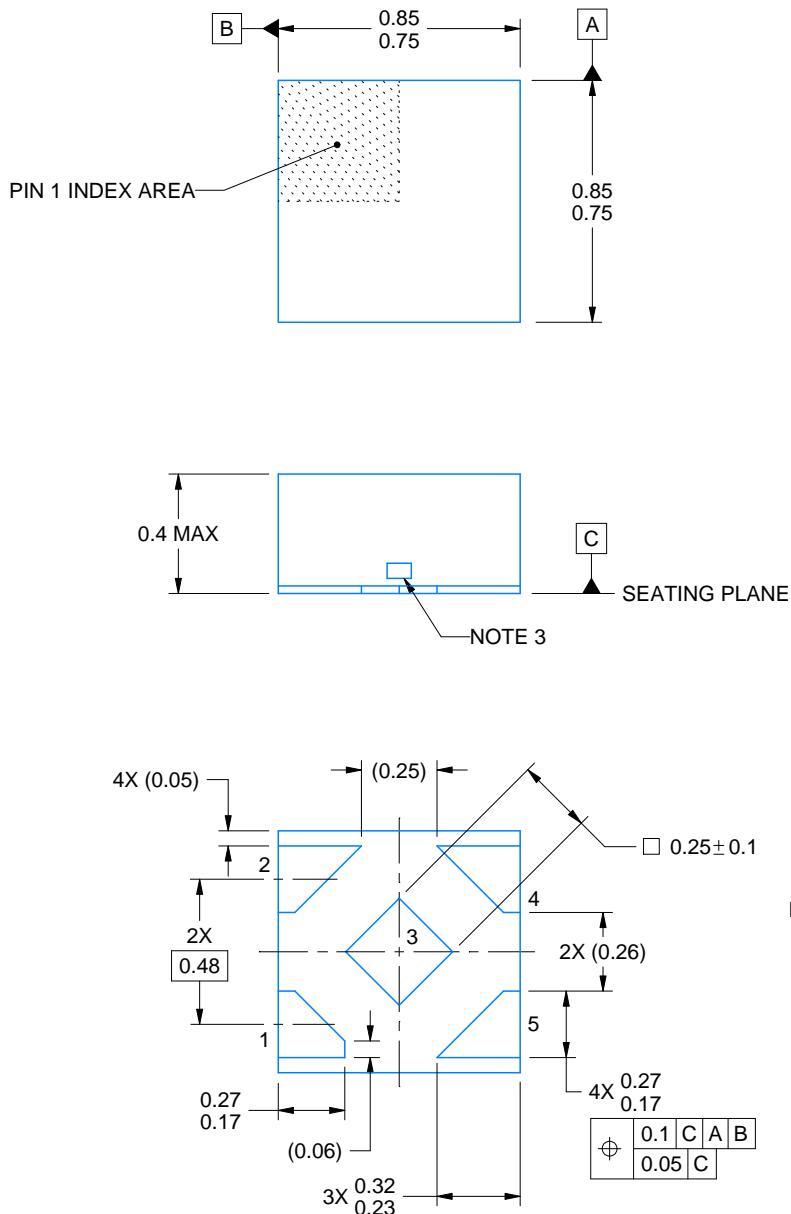
# PACKAGE OUTLINE

DPW0005A



X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



4223102/B 09/2017

NOTES:

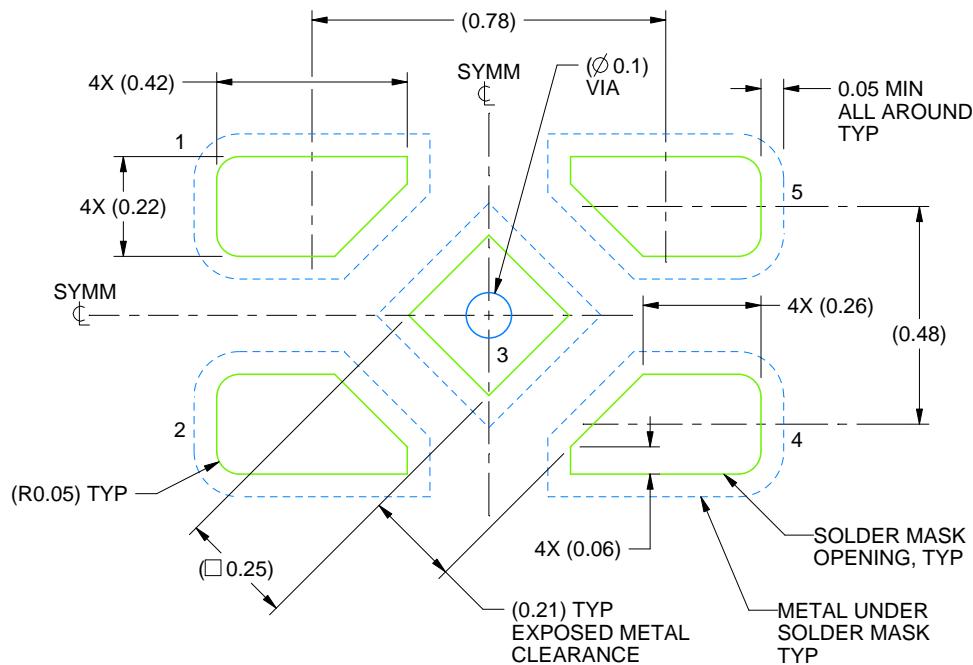
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The size and shape of this feature may vary.

## EXAMPLE BOARD LAYOUT

**DPW0005A**

## **X2SON - 0.4 mm max height**

## PLASTIC SMALL OUTLINE - NO LEAD



LAND PATTERN EXAMPLE  
SOLDER MASK DEFINED  
SCALE:60X

4223102/B 09/2017

NOTES: (continued)

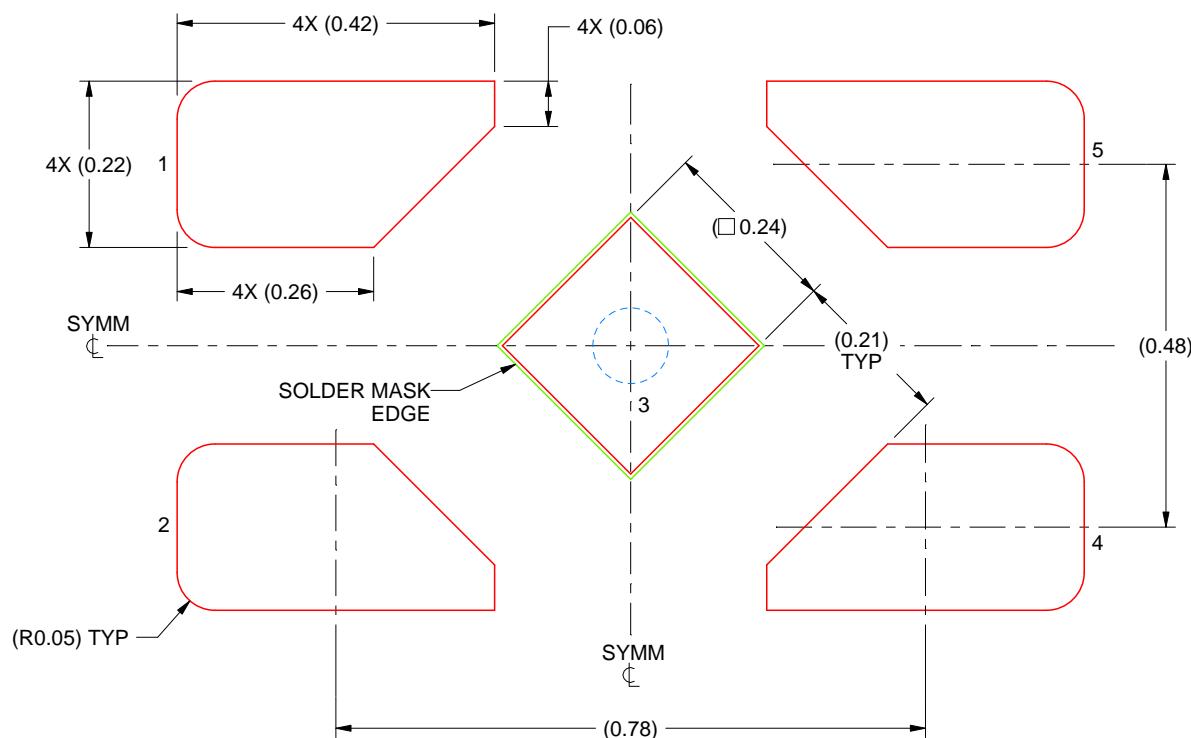
4. This package is designed to be soldered to a thermal pad on the board. For more information, refer to QFN/SON PCB application note in literature No. SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).

# EXAMPLE STENCIL DESIGN

DPW0005A

X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE  
BASED ON 0.1 mm THICK STENCIL

EXPOSED PAD  
92% PRINTED SOLDER COVERAGE BY AREA  
SCALE:100X

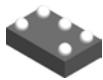
4223102/B 09/2017

NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

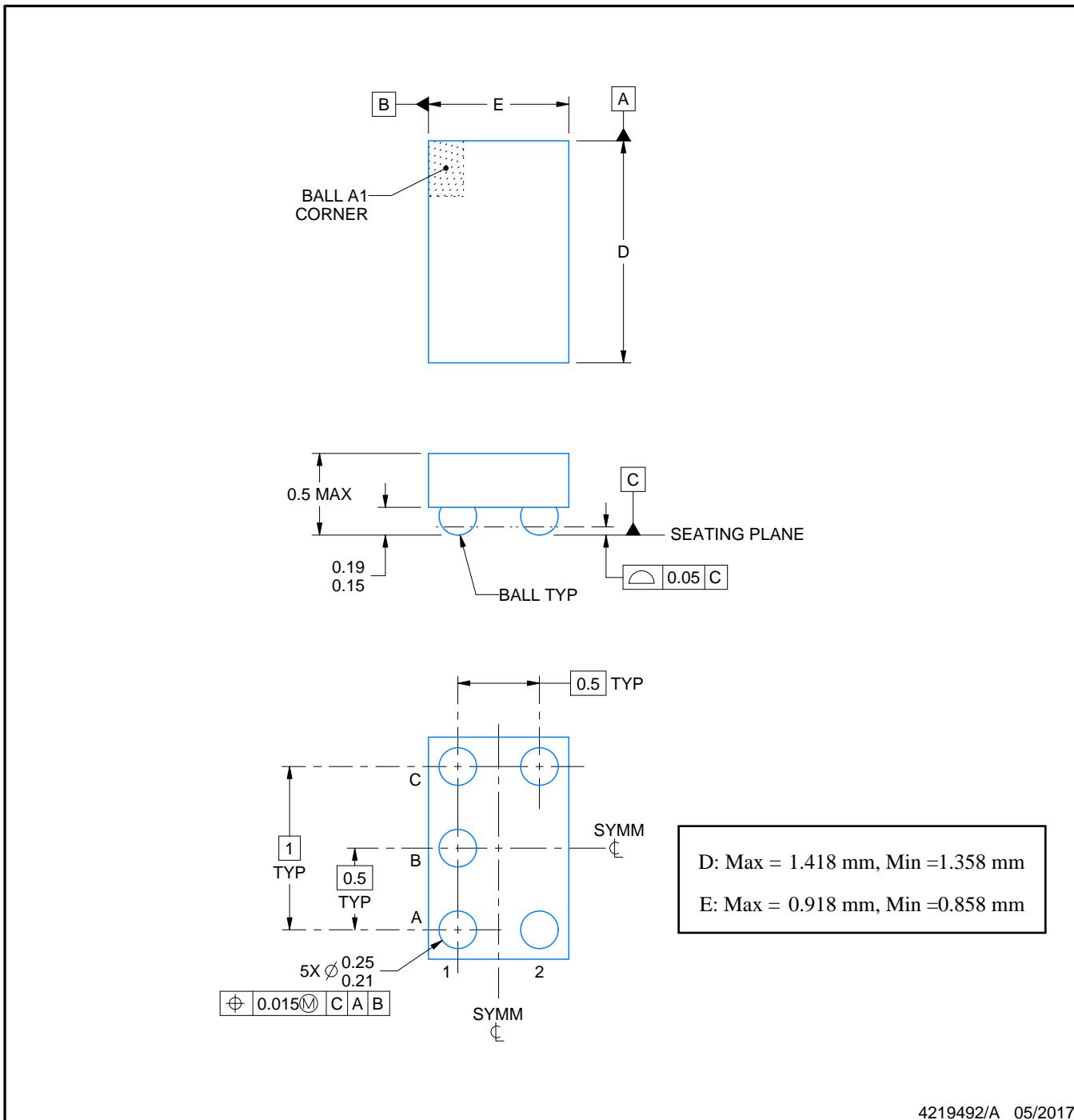
# PACKAGE OUTLINE

YZP0005



DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



## NOTES:

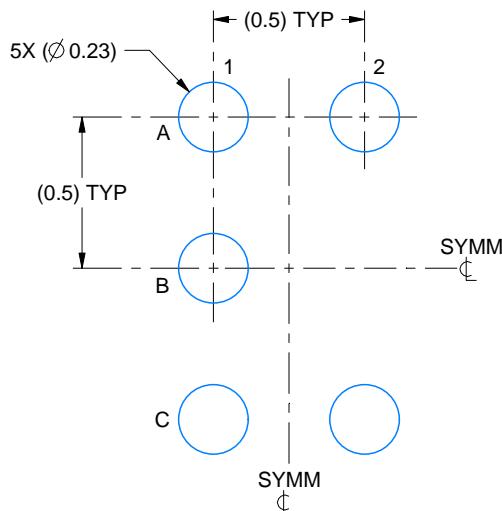
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

# EXAMPLE BOARD LAYOUT

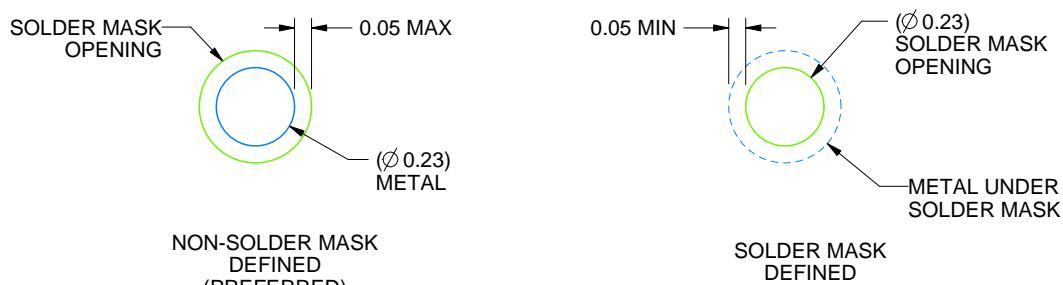
YZP0005

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



LAND PATTERN EXAMPLE  
SCALE:40X



SOLDER MASK DETAILS  
NOT TO SCALE

4219492/A 05/2017

NOTES: (continued)

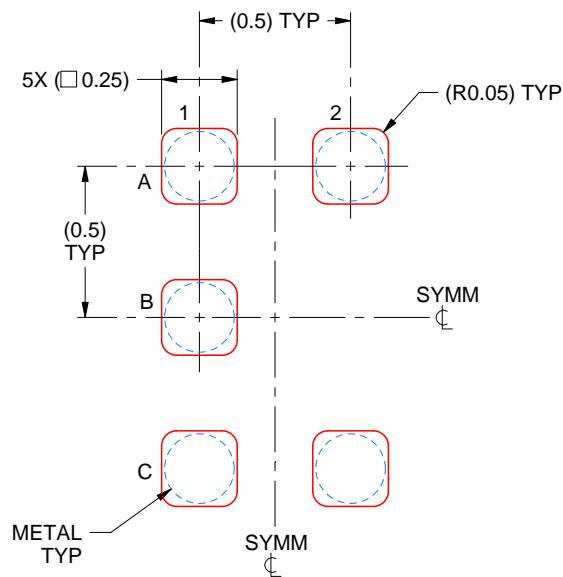
3. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For more information, see Texas Instruments literature number SNVA009 ([www.ti.com/lit/snva009](http://www.ti.com/lit/snva009)).

# EXAMPLE STENCIL DESIGN

YZP0005

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



SOLDER PASTE EXAMPLE  
BASED ON 0.1 mm THICK STENCIL  
SCALE:40X

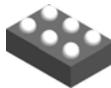
4219492/A 05/2017

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

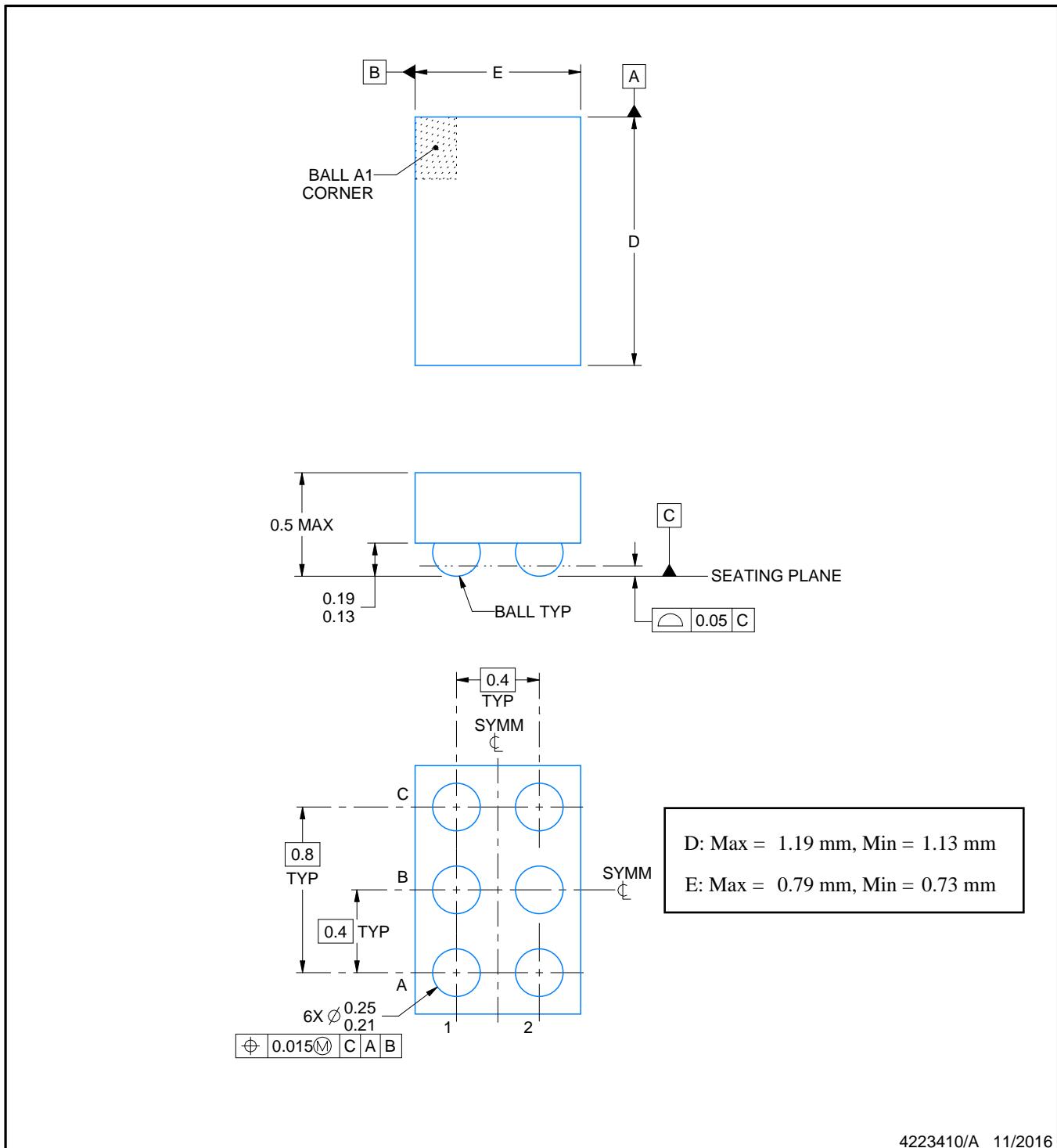
# PACKAGE OUTLINE

**YFP0006**



**DSBGA - 0.5 mm max height**

DIE SIZE BALL GRID ARRAY



4223410/A 11/2016

**NOTES:**

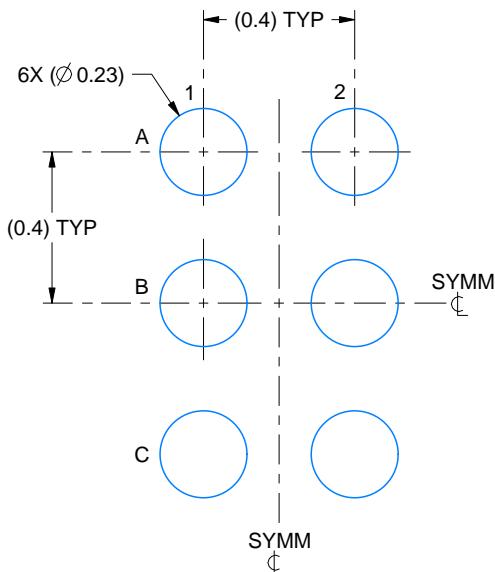
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

# EXAMPLE BOARD LAYOUT

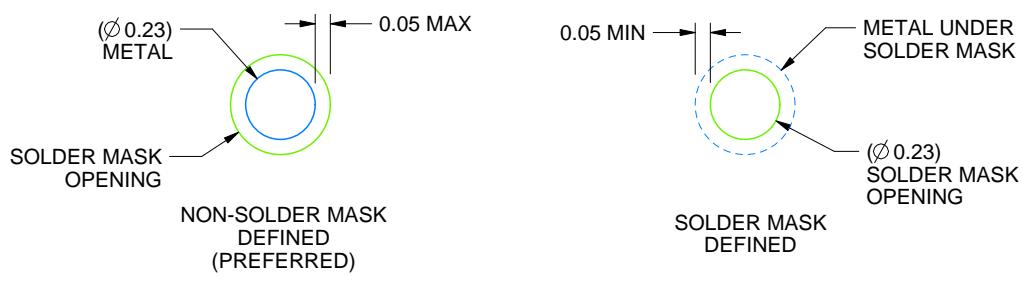
YFP0006

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



LAND PATTERN EXAMPLE  
SCALE:50X



SOLDER MASK DETAILS  
NOT TO SCALE

4223410/A 11/2016

NOTES: (continued)

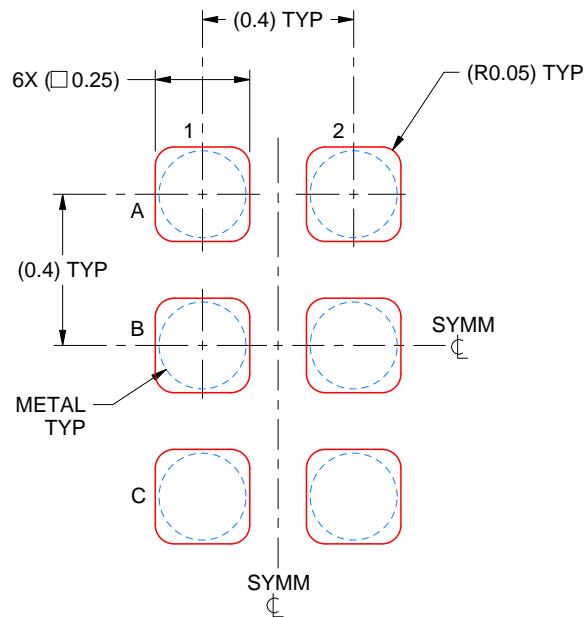
3. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints.  
For more information, see Texas Instruments literature number SNVA009 ([www.ti.com/lit/snva009](http://www.ti.com/lit/snva009)).

# EXAMPLE STENCIL DESIGN

YFP0006

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



SOLDER PASTE EXAMPLE  
BASED ON 0.1 mm THICK STENCIL  
SCALE:50X

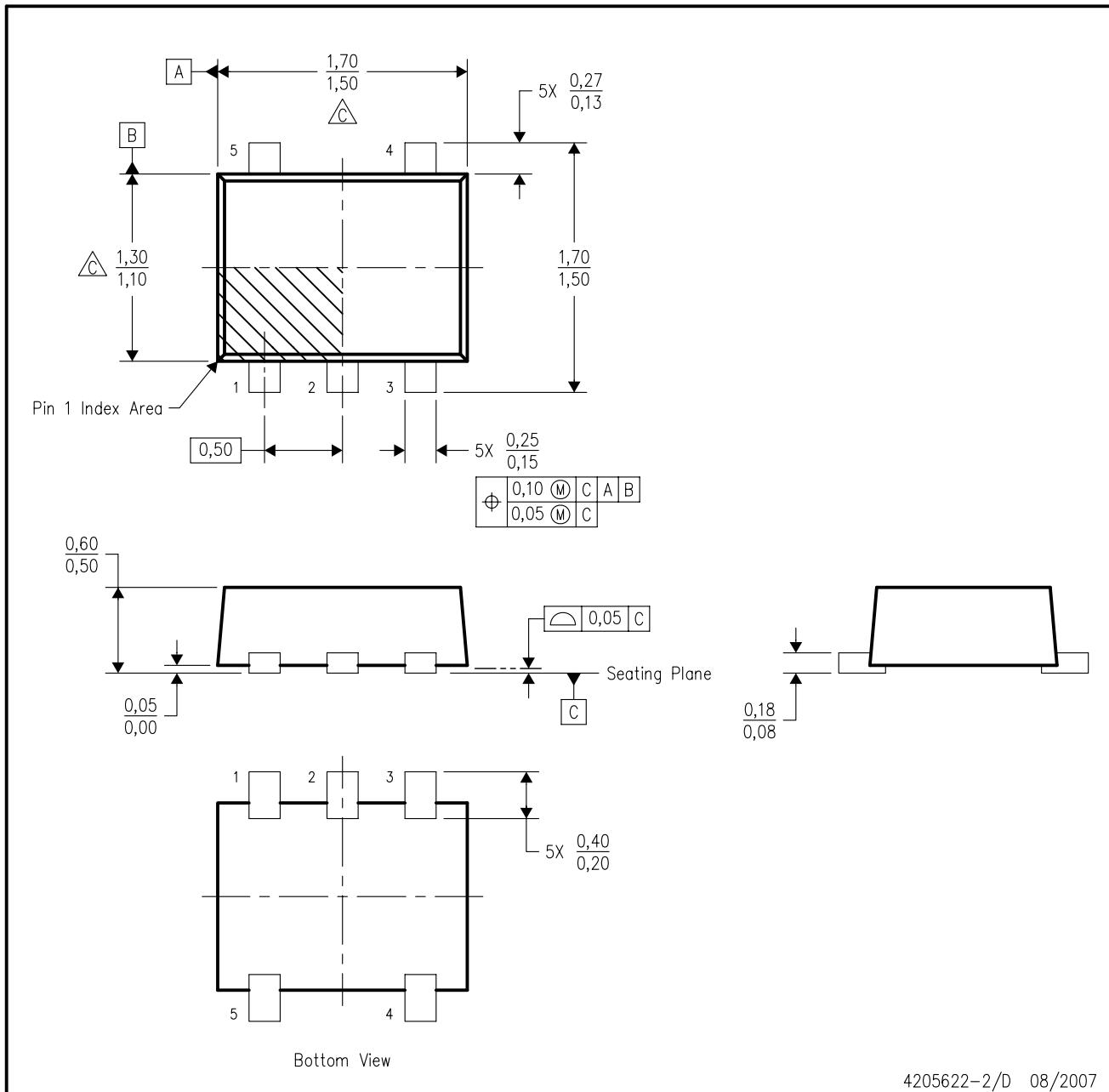
4223410/A 11/2016

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

## DRL (R-PDSO-N5)

## PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.  
B. This drawing is subject to change without notice.

 THIS DRAWING IS SUBJECT TO CHANGE WITHOUT NOTICE.

 Body dimensions do not include mold flash, interlead flash, protrusions, or gate burrs. Mold flash, interlead flash, protrusions, or gate burrs shall not exceed 0,15 per end or side.

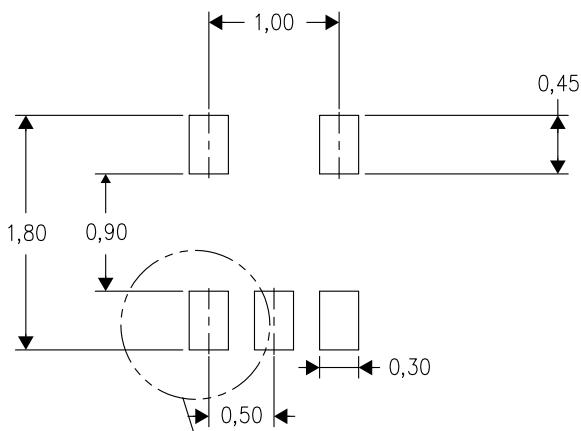
D. JEDEC package registration is pending.

D. JEDEC package registration is pending.

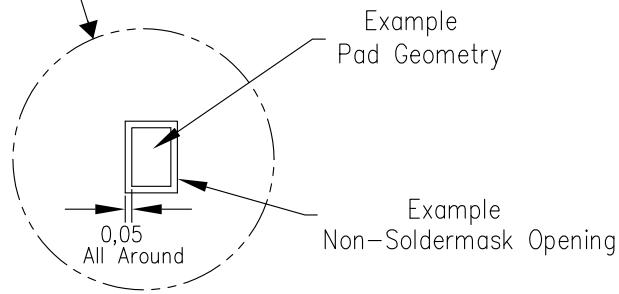
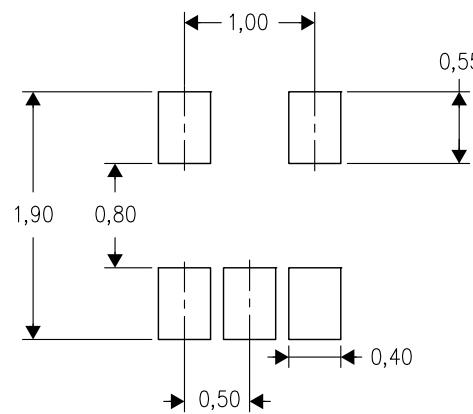
DRL (R-PDSO-N5)

PLASTIC SMALL OUTLINE

Example Board Layout



Example Non-Soldermask Defined Pad

Example Stencil Design  
(Note E)

4208207-2/E 06/12

NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Publication IPC-7351 is recommended for alternate designs.
- Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.
- Maximum stencil thickness 0,127 mm (5 mils). All linear dimensions are in millimeters.
- Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
- Side aperture dimensions over-print land for acceptable area ratio  $> 0.66$ . Customer may reduce side aperture dimensions if stencil manufacturing process allows for sufficient release at smaller opening.

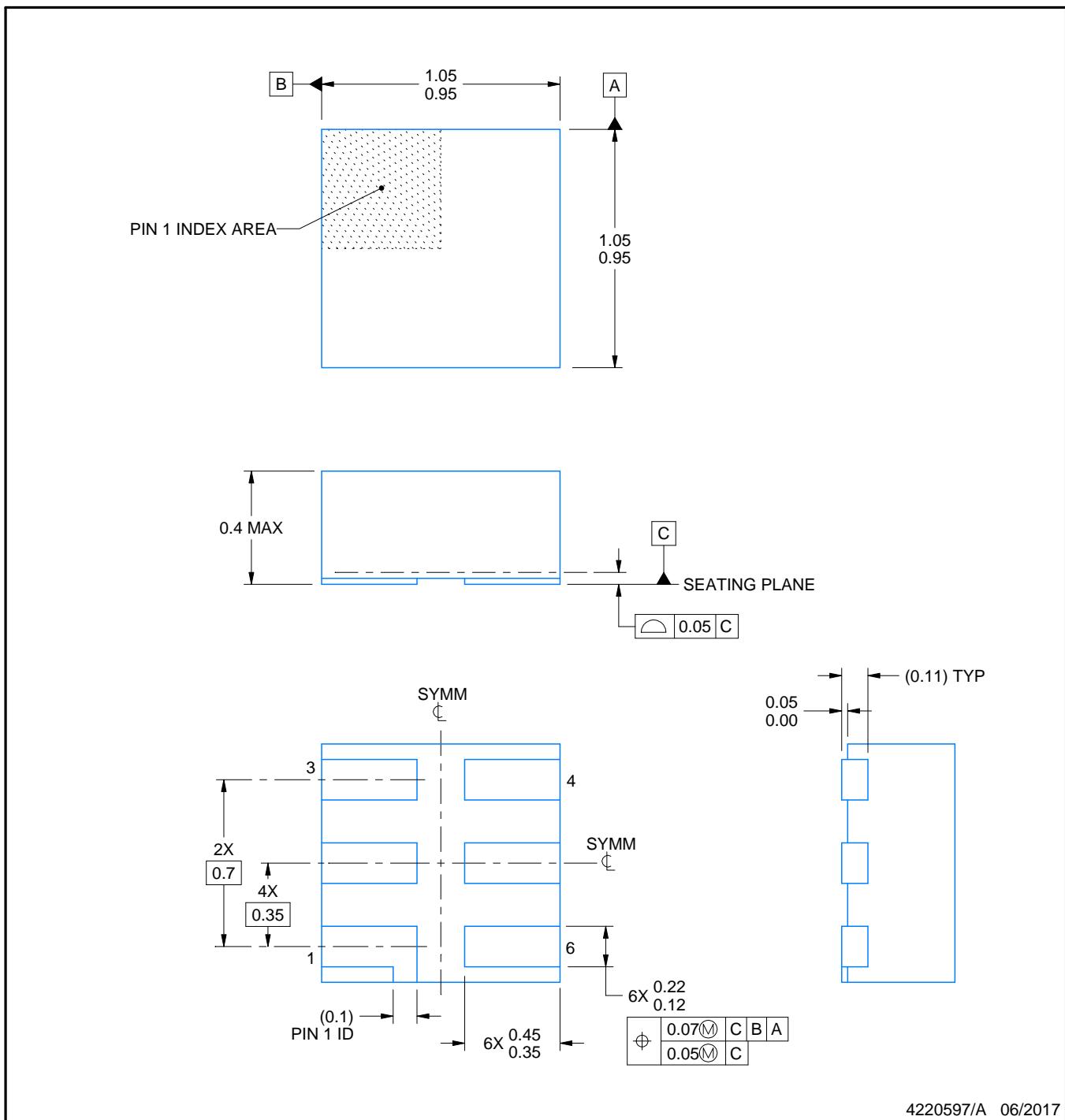
# PACKAGE OUTLINE

DSF0006A



X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



## NOTES:

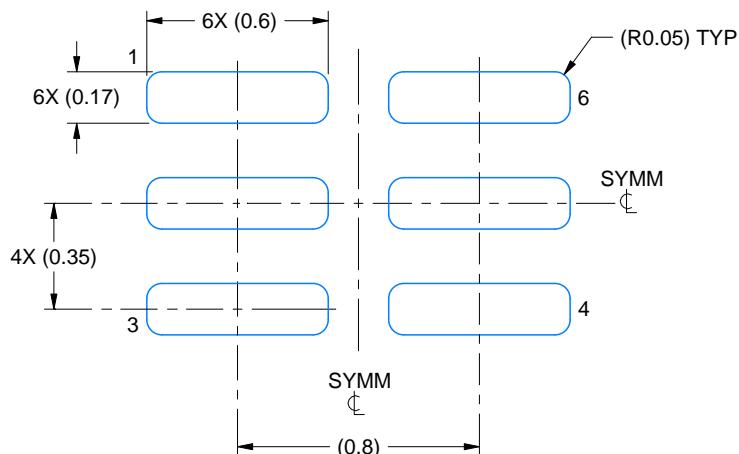
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC registration MO-287, variation X2AAF.

# EXAMPLE BOARD LAYOUT

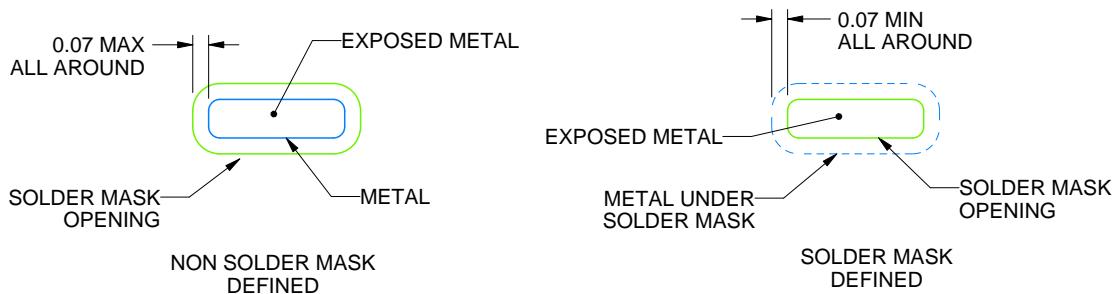
DSF0006A

X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:40X



SOLDER MASK DETAILS

4220597/A 06/2017

NOTES: (continued)

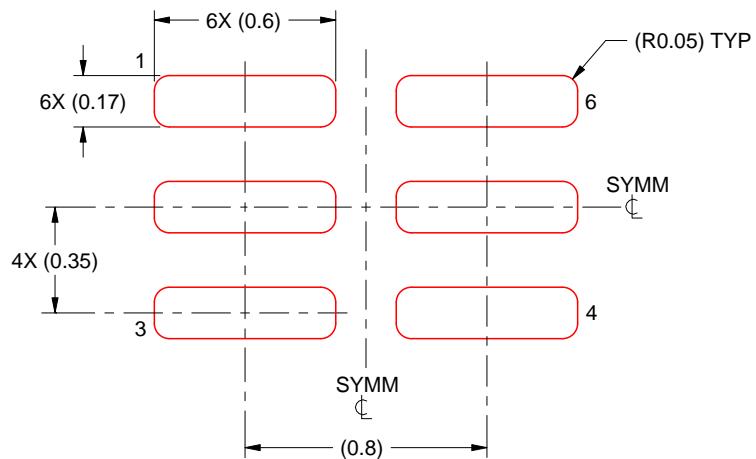
4. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).

# EXAMPLE STENCIL DESIGN

DSF0006A

X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL

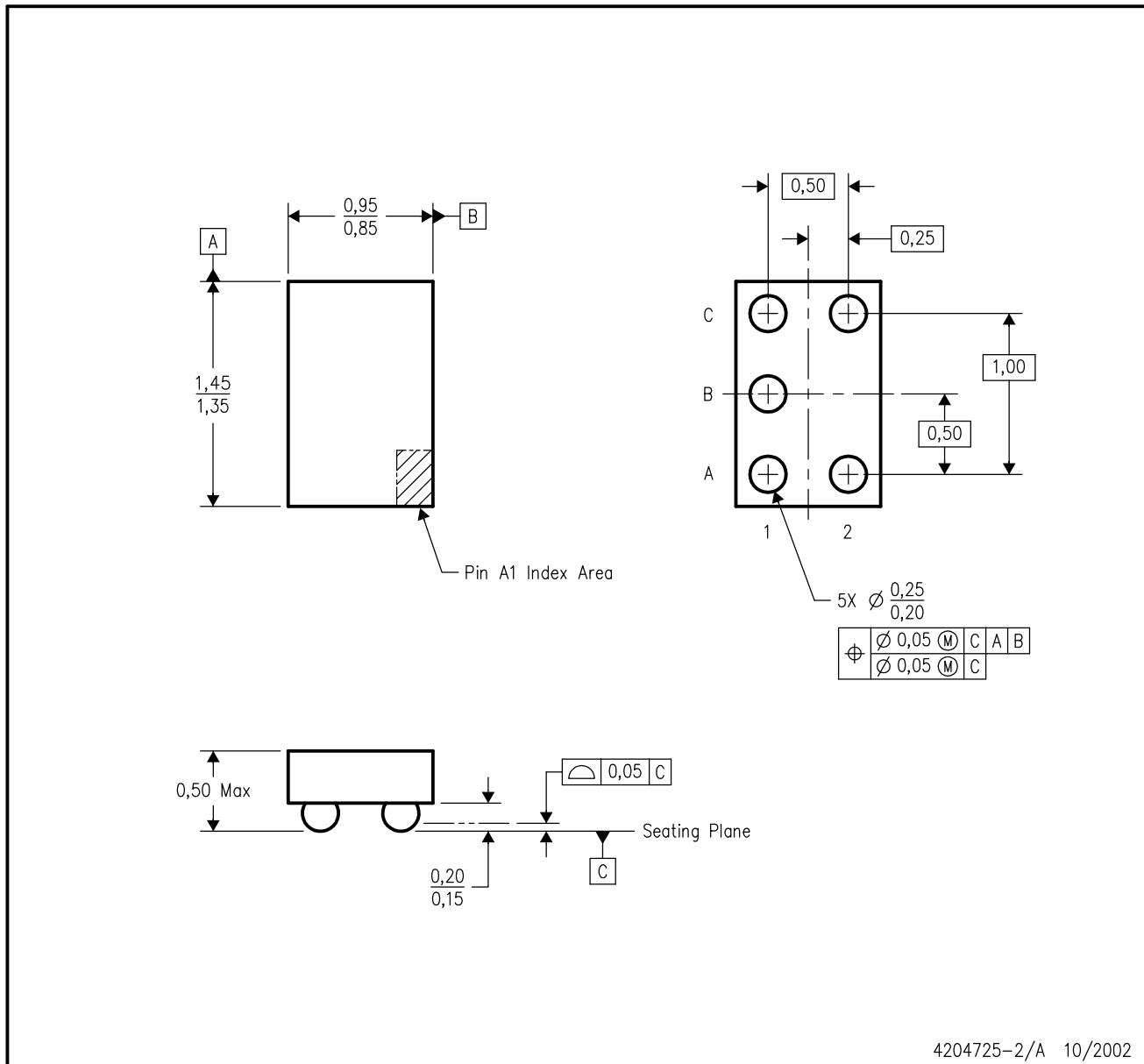
PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE  
SCALE:40X

4220597/A 06/2017

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

## YEP (R-XBGA-N5)

## DIE-SIZE BALL GRID ARRAY



4204725-2/A 10/2002

NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- NanoStar™ package configuration.
- This package is tin-lead (SnPb). Refer to the 5 YZP package (drawing 4204741) for lead-free.

NanoStar is a trademark of Texas Instruments.

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